

ECE 124a/256c

MOS Gate Models



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Gronoski



Basics (MOS Electrical Model)

$$I_{ds} = \frac{kW}{L} \left((V_{gs} - V_T)V_F - \frac{V_F^2}{2} \right) (1 + \lambda V_{ds})$$

- Nonlinear model with 3 conduction modes:
 - Linear Mode ($V_{ds} < V_{gs} - V_T$) and ($V_{ds} < V_{sat}$): $V_F = V_{ds}$
 - Saturation ($V_{ds} > V_{gs} - V_T$) and ($V_{ds} < V_{sat}$): $V_F = V_{gs} - V_T$
 - Velocity Saturation ($V_{ds} > V_{sat}$): $V_F = V_{sat}$
- $V_F = \text{Min}(V_{gs} - V_T, V_{sat}, V_{ds})$



Body Effect

- Threshold is function of back potential
 - Increases difficulty of turn on for junction reverse bias increase

0.18 μ	Φ_f	γ
N-type	0.4 (V)	0.32
P-type	0.4 (V)	-0.42

$$V_T = V_{T0} + \gamma \left(\sqrt{2|\phi_f| + V_{SB}} - \sqrt{2|\phi_f|} \right)$$

$$\phi_f = \frac{kT}{q} \ln \left(\frac{N_a}{n_i} \right)$$

$$\gamma = \frac{\sqrt{2q\epsilon_{Si}N_a}}{C_{ox}}$$

Velocity Saturation

- Carrier Velocity Saturates at about $1.7 \times 10^7 \text{ cm/s}$
- For short channel (small L) this occurs at V_{sat}
- Mobility (μ) is a function of doping and temperature

0.18 μ	μ	V_{sat}
N-type	400 (cm^2/Vs)	0.8V
P-type	150 (cm^2/Vs)	2.2V

$$V_{\text{sat}} = \frac{(1.7 \times 10^7 \text{ cm/s})L(\text{cm})}{\mu(\text{cm}^2 / \text{Vs})}$$

$$\mu(T) = \mu(300\text{K})(T / 300)^{-3/2}$$

MOS Capacitors

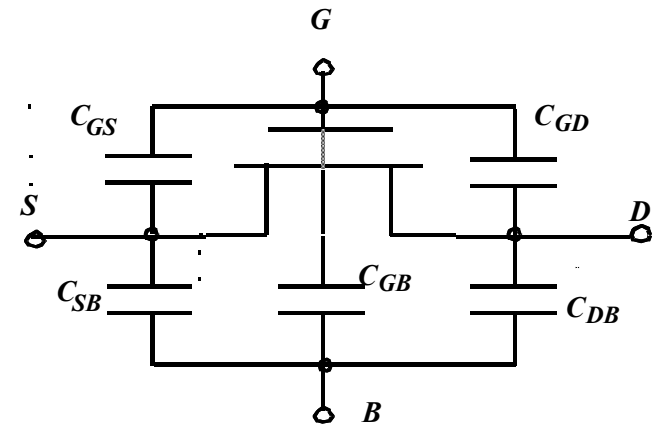
- Gate (assume constant) = $\epsilon_{Si} WL/t_{ox}$
- Source/Drain
 - Bottom (Area) $C_j m_j$
 - SideWall (Perimeter) $C_{jsw} m_{jsw}$
- Equivalent Capacitance (Swing V_{low} to V_{high})

$$C_{eq} = \frac{\Delta Q_j}{\Delta V_D} = \frac{Q_j(V_{high}) - Q_j(V_{low})}{V_{high} - V_{low}} = K_{eq} C_{j0}$$

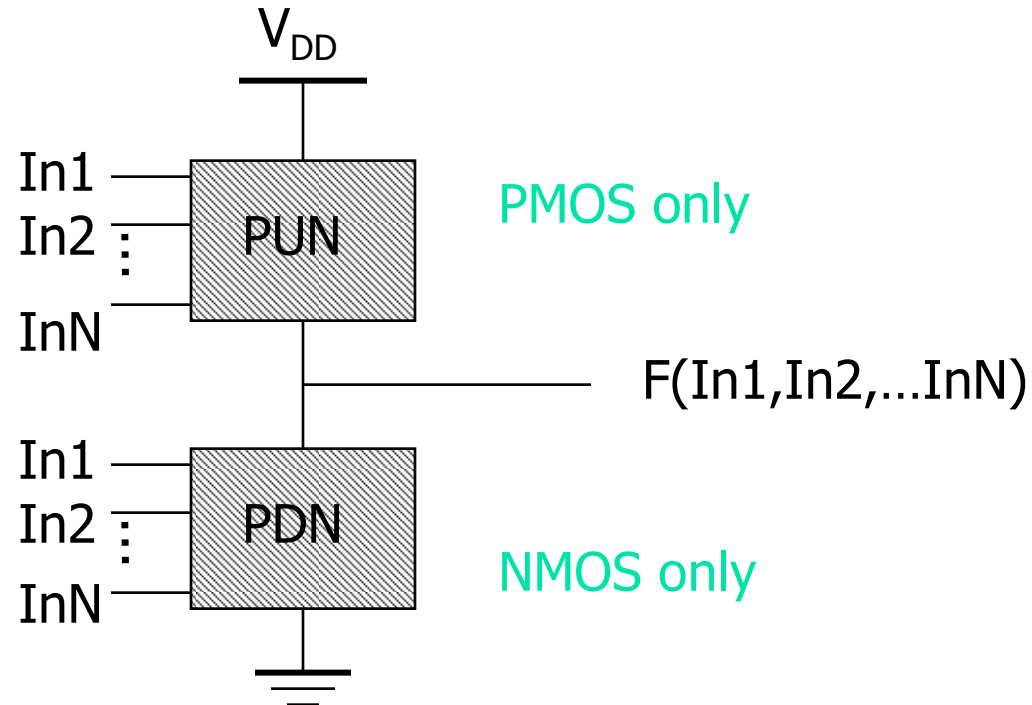
$$K_{eq} = \frac{-\phi_0^m}{(V_{high} - V_{low})(1 - m)} [(\phi_0 - V_{high})^{1-m} - (\phi_0 - V_{low})^{1-m}]$$

Transient Capacitor Parasitics

- Only capacitors which change potential over the swing are included.
- C_{gs} and C_{gd} are often modeled as C_g and C_{gso} , C_{gdo} . C_{gdo} models the feed through (input to output) capacitance
- For low swing rates, double C_{gdo}
- For high swing rates, start the output swing from the offset output voltage
 - C_{gdo} and C_{load} produce a capacitive voltage divider.

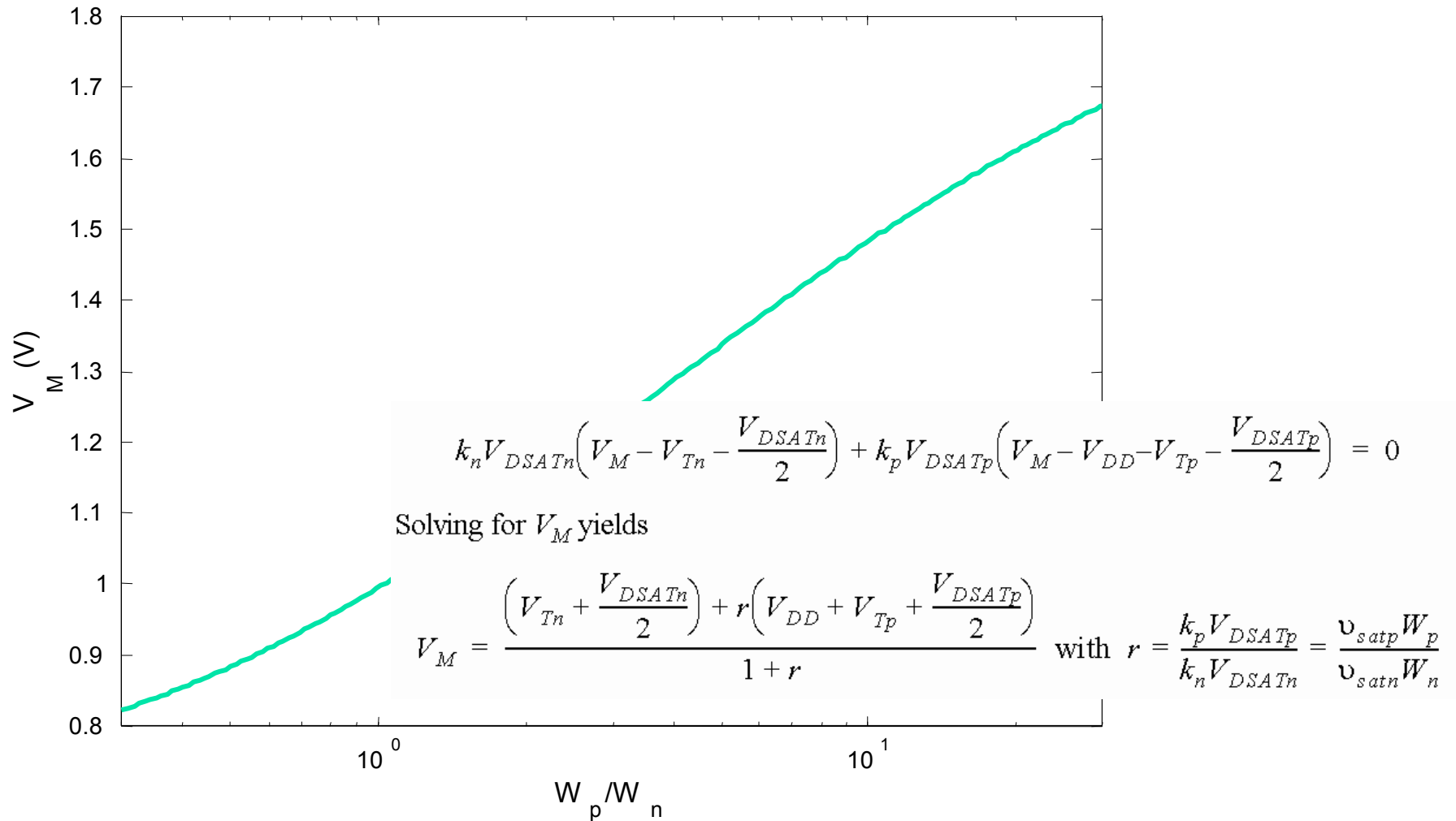


Static Complementary CMOS

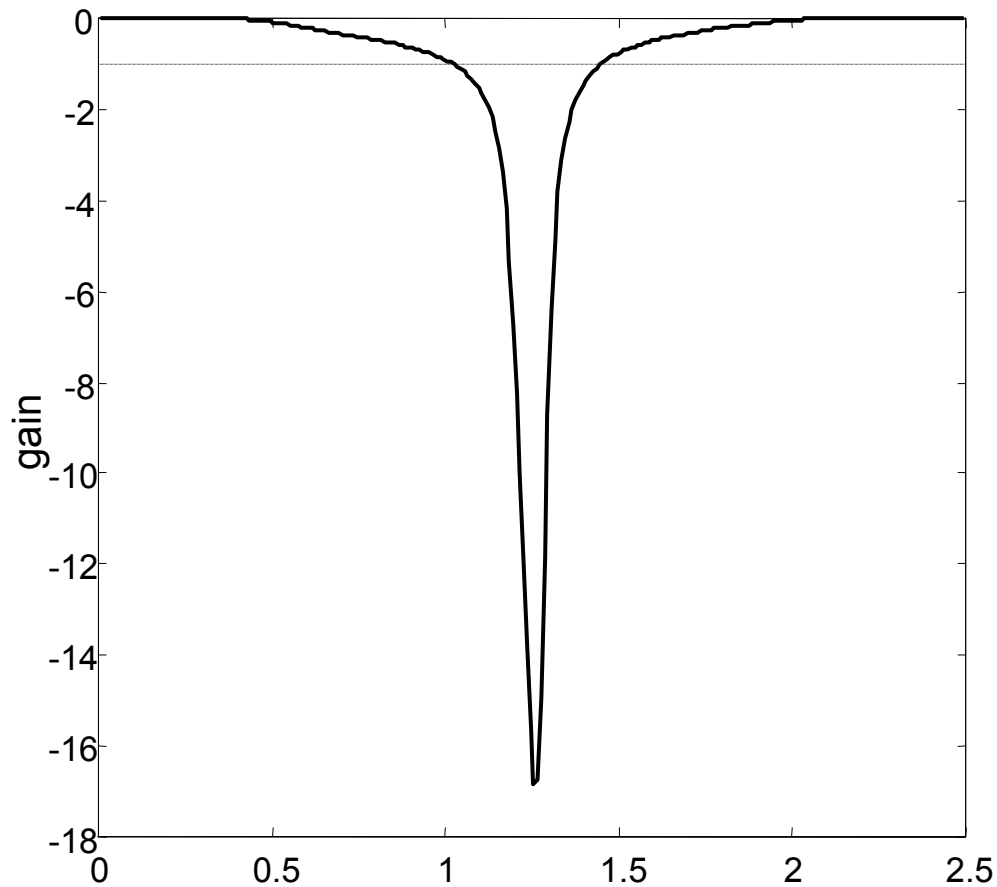


PUN and PDN are **logically dual** logic networks

Inverter Threshold vs. N/P Ratio

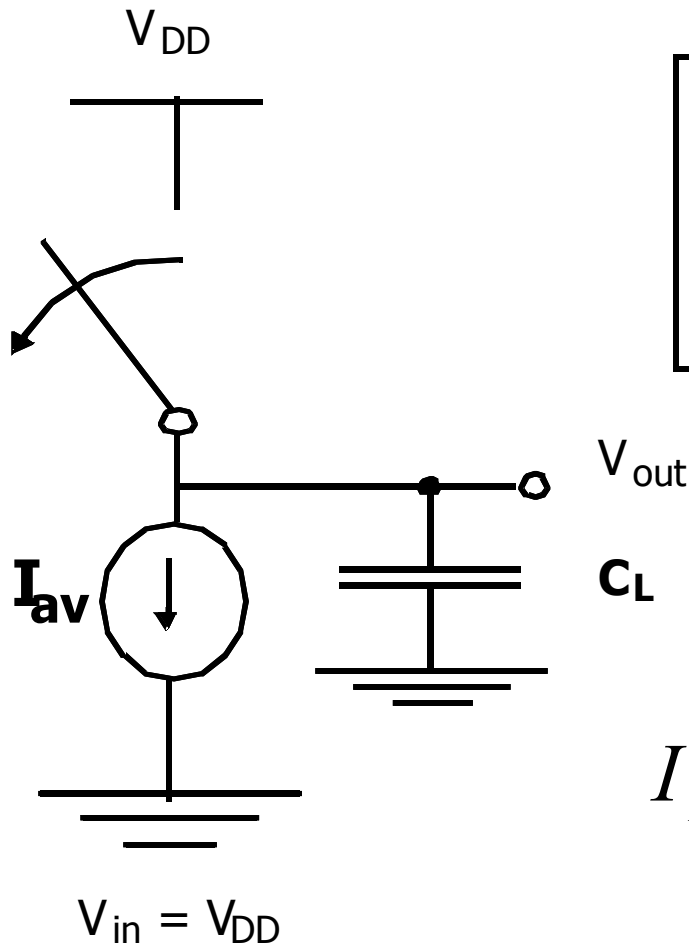


Inverter Gain



$$\text{gain} = \frac{-1}{I_D(V_M)} \frac{k_n V_{DSAT(n)} + k_p V_{DSAT(p)}}{\lambda_n - \lambda_p}$$
$$\approx \frac{1+r}{(V_M - V_{Tn} - V_{DSAT(n)} / 2)(\lambda_n - \lambda_p)}$$

CMOS Inverter Propagation Delay

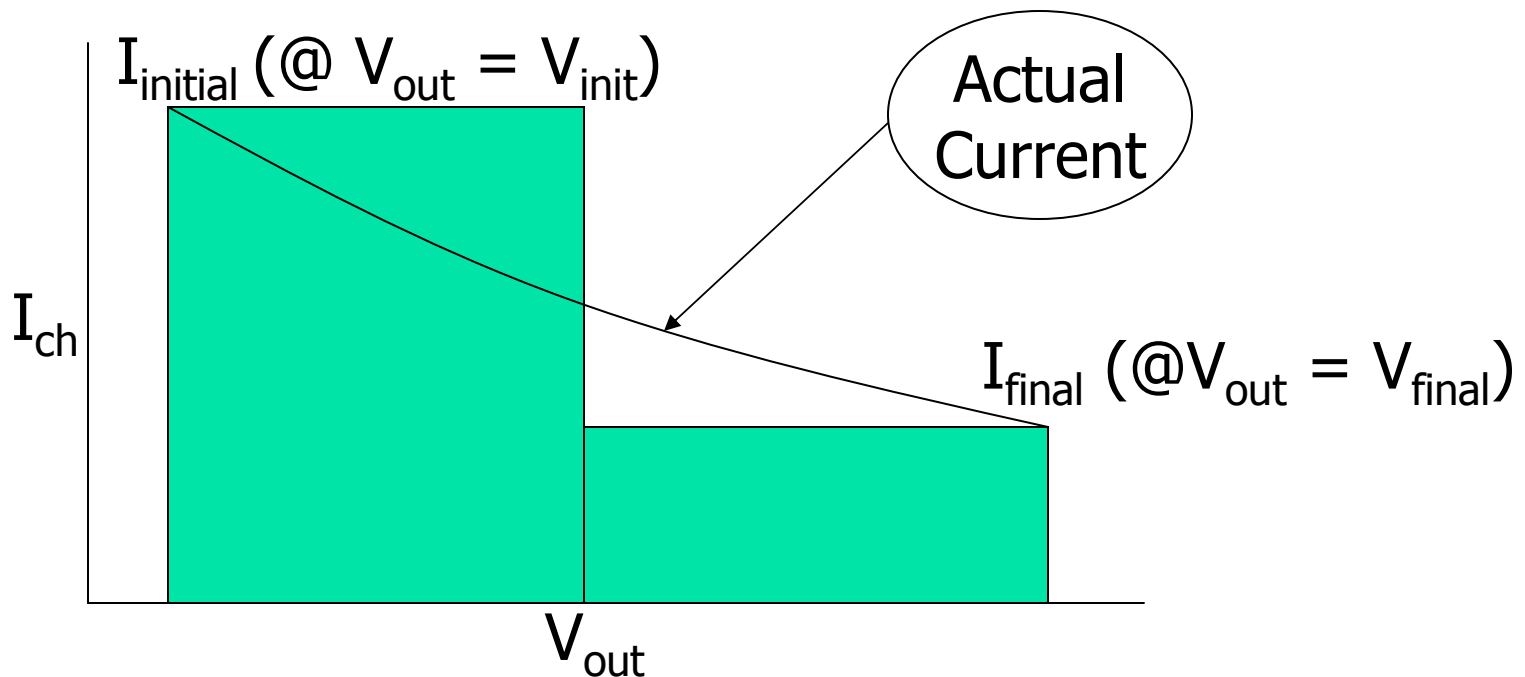


$$t_{pHL} = \frac{C_L V_{swing}/2}{I_{av}}$$

$$I_{AV} \approx \frac{I_{ds}(init) + I_{ds}(final)}{2}$$

Approximating I_{avg}

- Prescription from Hodges and Jackson
 - Assume input rise is instantaneous: ignore rise-time effects
- Average charging current at endpoints of swing
 - Initial point is usually a supply rail, final point is threshold of next gate

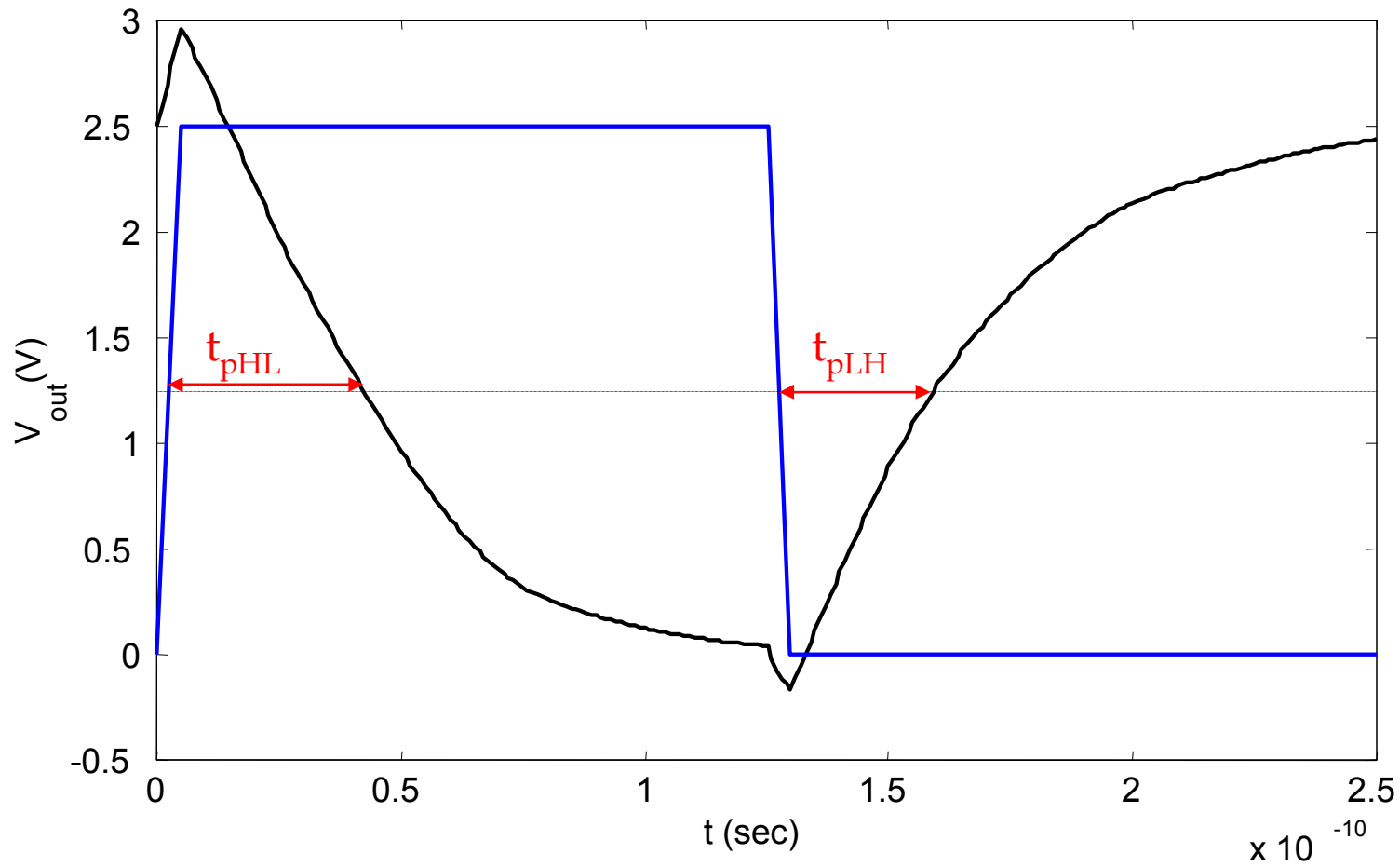




Hodges-Jackson Current Averaging

- FET's act as a current source
- Simple model for full-swing current:
 - I_1 is initial current at start of swing
 - I_2 is current at threshold of next stage
 - I_{avg} is approximated by $(I_1+I_2)/2$
- Delay $t = \frac{C\Delta V}{I_{avg}} = CR_{eff} = 0.69CR_{eq}$

Transient Response





Constructing a Complex Gate

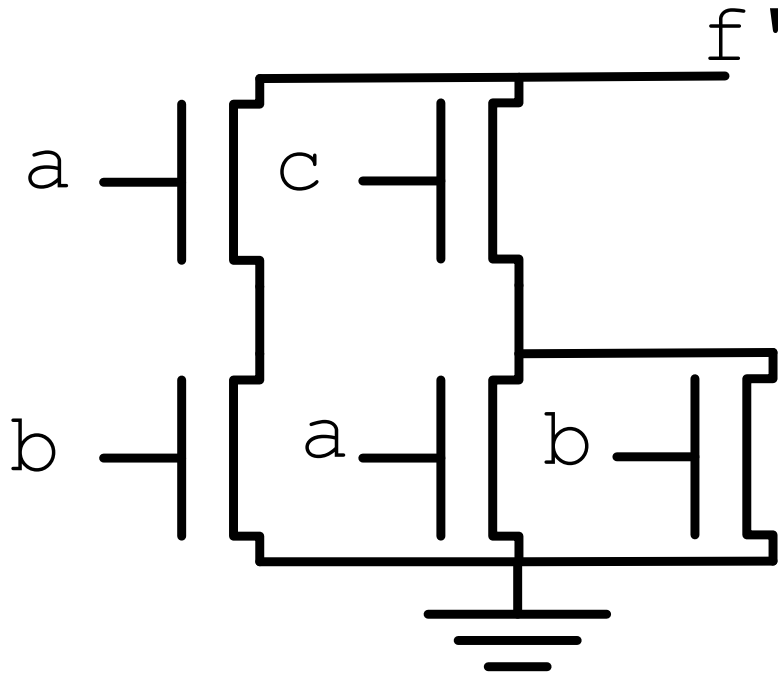
- Logic Dual need **not** be Series/Parallel Dual
- In general, many logical dual exist, need to choose one with best characteristics
- Use Karnaugh-Map to find good duals
 - Goal: find 0-cover and 1-cover with best parasitic or layout properties
 - Maximize connections to power/ground
 - Place critical transistors closest to output node
 - Know the order of arrival of signals! – order the transitions if possible

Example: Carry Gate

	c	c'
AB	0	0
AB'	0	1
A'B'	1	1
A'B	0	1

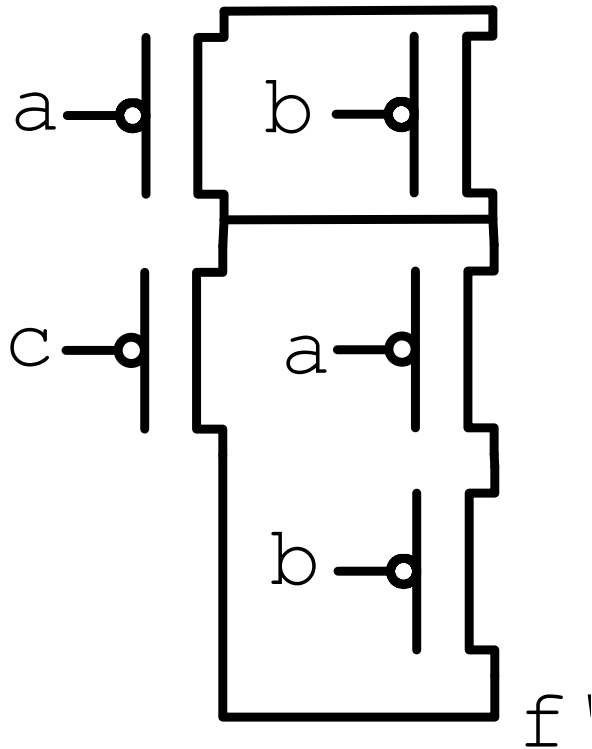
- $F = (ab+bc+ac)'$
- Carry 'c' is critical
- Factor c out: (Why c?)
- $F=(ab+c(a+b))'$
- **0-cover** is n-pull up
- **1-cover** is p-pull down

Example: Carry Gate (2)



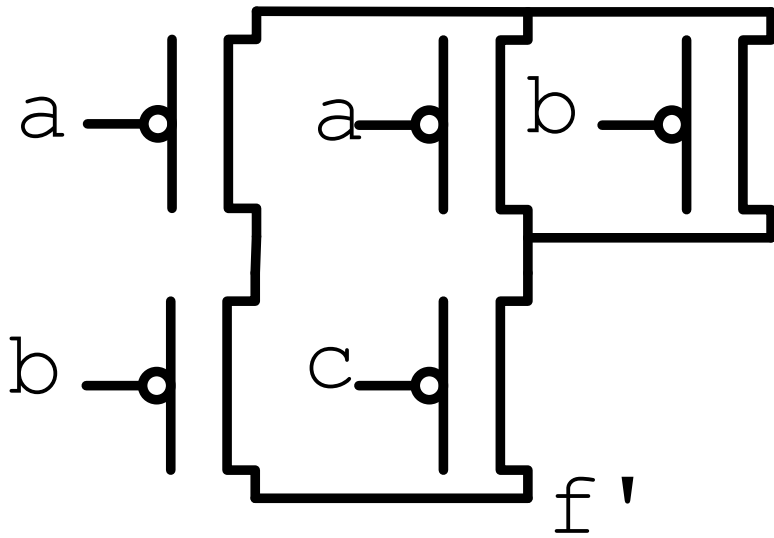
- Pull Down is easy
- Order by maximizing connections to ground and critical transistors
- For pull up – Might guess series parallel graph dual– but would guess wrong

Example: Carry Gate (3)



- Series/Parallel Dual
- 3-series transistors
- 2 connections to Vdd
- 7 floating capacitors

Example: Carry Gate (4)



- Pull Up from 1 cover of Kmap
 - Get $a'b' + a'c' + b'c'$
 - Factor c' out
- 3 connections to Vdd
- 2 series transistors
- Co-Euler path layout
- Moral: Use Kmap!

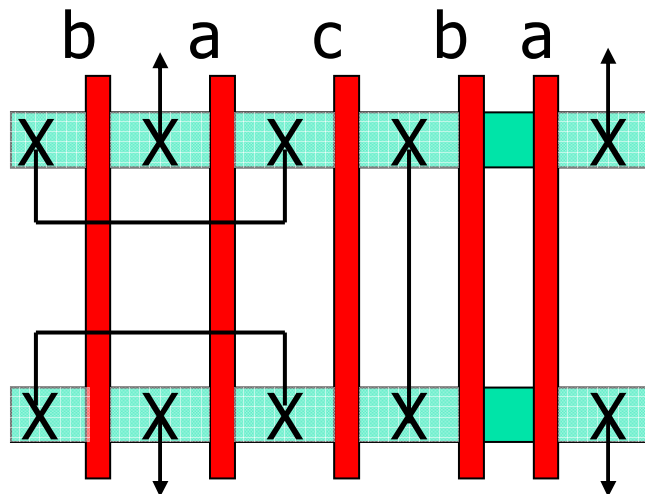
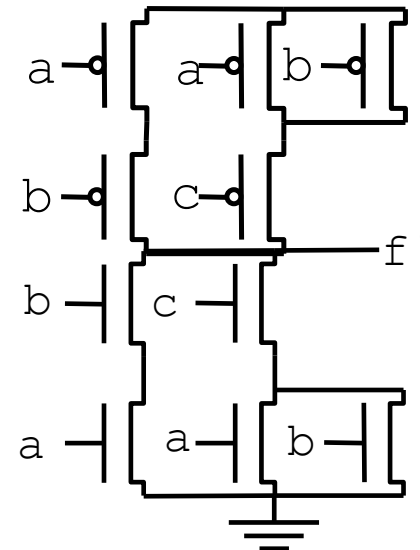


Euler Path

- For CMOS standard cell, and Euler path often helps to organize the transistor order so that a faster, more dense cell can be constructed.
- Ideally, the p-fet and n-fet sub-circuits can be traversed in identical transistor orders to create a layout without diffusion (thinox) gaps.
- Euler Path:
 - Traversal of entire schematic (every transistor) without traversing any transistor twice.
 - Possible only if 0 or 2 odd nodes in schematics. Node count is the number of transistors incident on a common point.
 - If 0, any point can be start (will also be end) of path, for 2, one of the odd nodes is the start and the other is the end.

Euler Path II

- Eg. Carry Gate
 - Path: b-a-c-b-a or a-b-c-a-b or ...
 - Can sometimes also minimize the routing by careful choice of order





Static Logic: Rules of Thumb

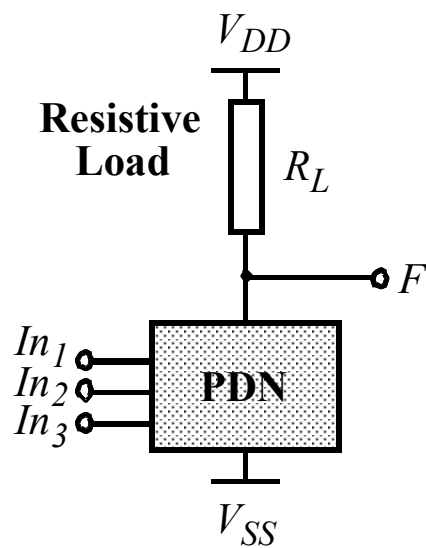
1. Step-up (alpha) ratio of 4 produces minimum power-delay product
2. P vs. N (beta) ratio of 2 balances pull-up and pull-down times and noise margins.
3. Approximately 75% of static logic are NAND stacks (limit stack to 3-4, use ordering and tapering for speed)



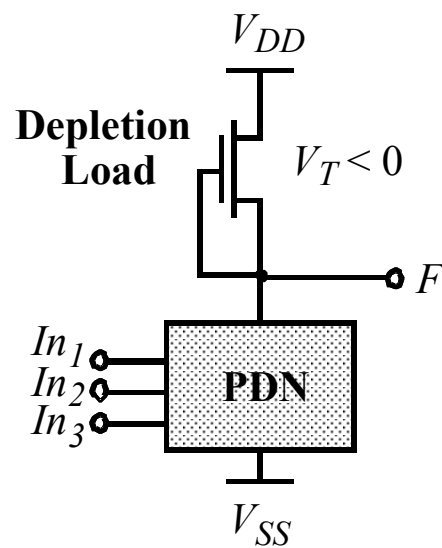
More Rules of Thumb

1. Glitches consume approximately 15% of overall chip power.
2. Crossover (short-circuit) current consumes $\sim 10\%$ of a static chip's total power (but is a function of input/output slews, ie sizing)

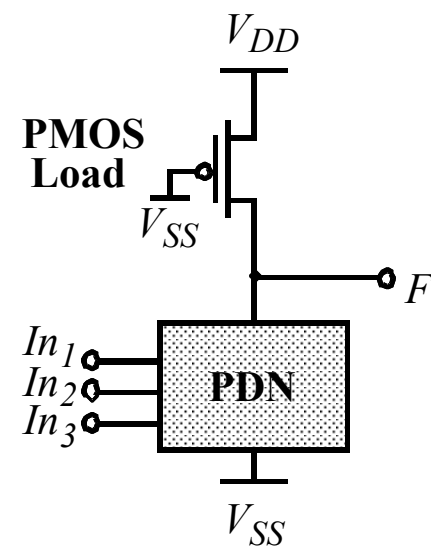
Ratio Logic



(a) resistive load



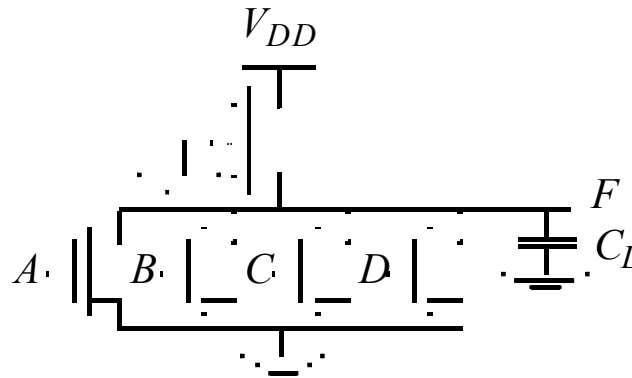
(b) depletion load NMOS



(c) pseudo-NMOS

Goal: to reduce the number of devices over complementary CMOS as a means to reduce parasitics (usually for performance).

Pseudo NMOS



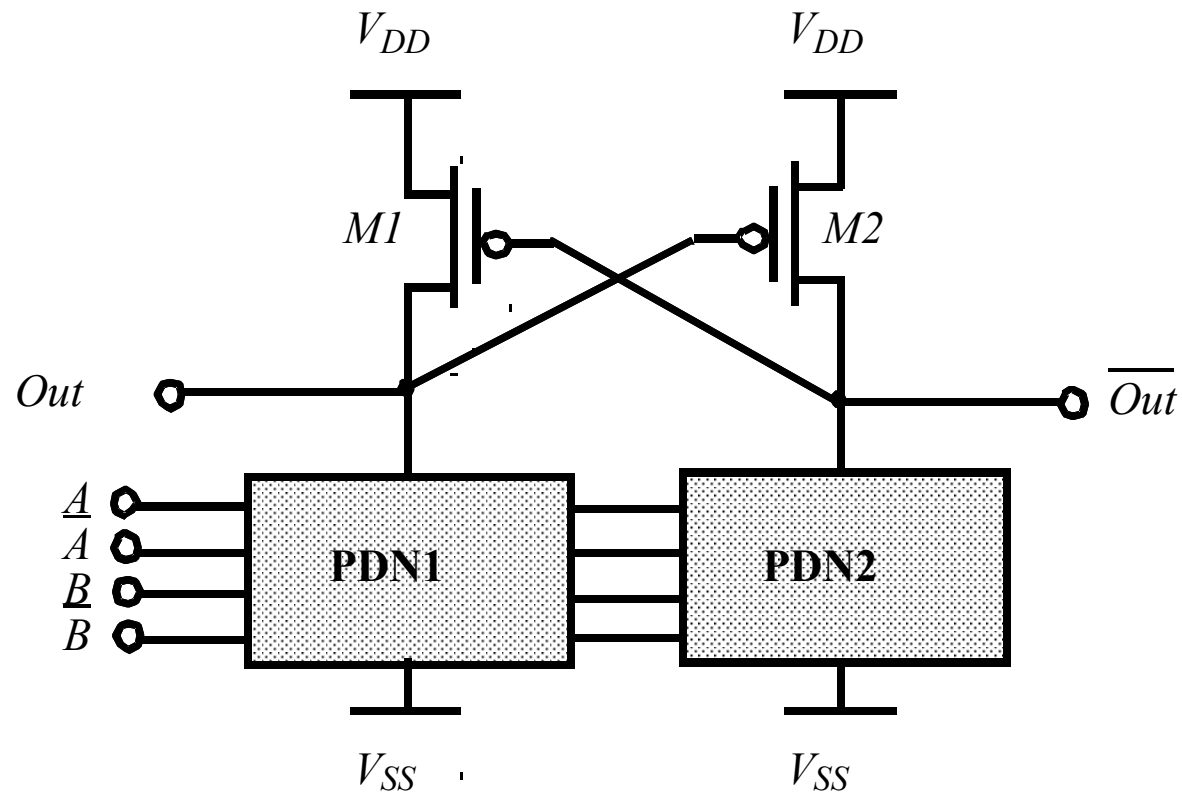
$V_{OH} = V_{DD}$ (similar to complementary CMOS)

$$k_n \left((V_{DD} - V_{Tn}) V_{OL} - \frac{V_{OL}^2}{2} \right) = \frac{k_p}{2} (V_{DD} - |V_{Tp}|)^2$$

$$V_{OL} = (V_{DD} - V_T) \left[1 - \sqrt{1 - \frac{k_p}{k_n}} \right] \text{ (assuming that } V_T = V_{Tn} = |V_{Tp}| \text{)}$$

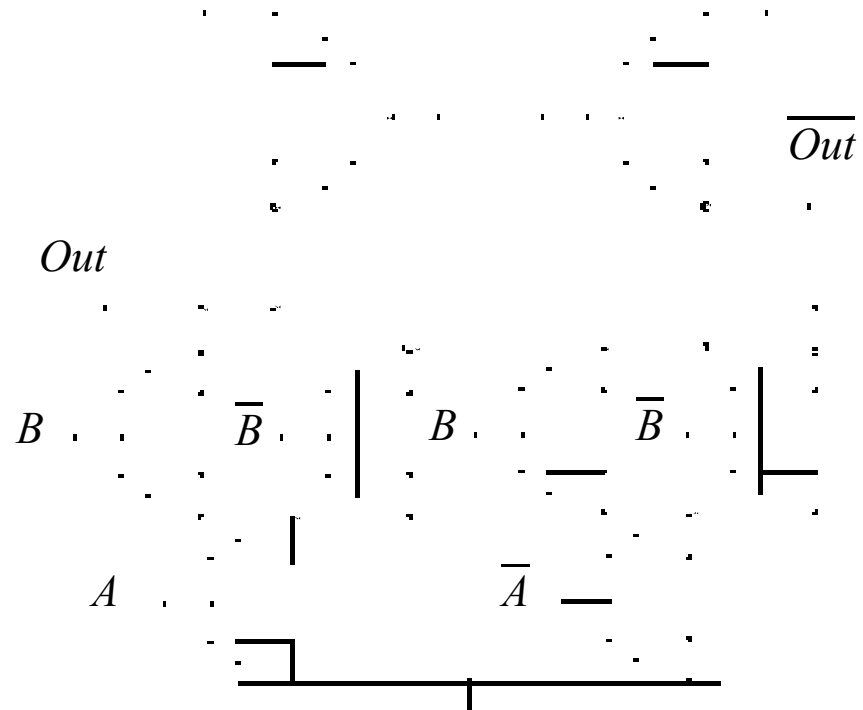
SMALLER AREA & LOAD BUT STATIC POWER DISSIPATION!!!

Even Better Noise Immunity/Density



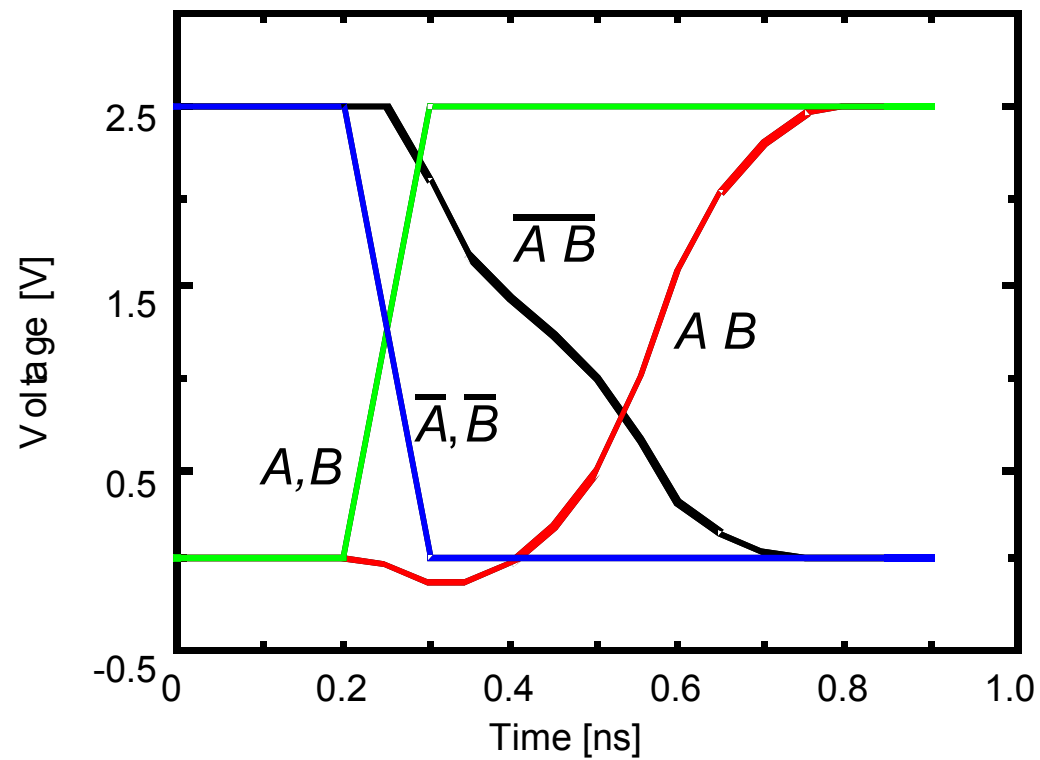
Differential Cascode Voltage Switch Logic (DCVSL)

DCVSL Example

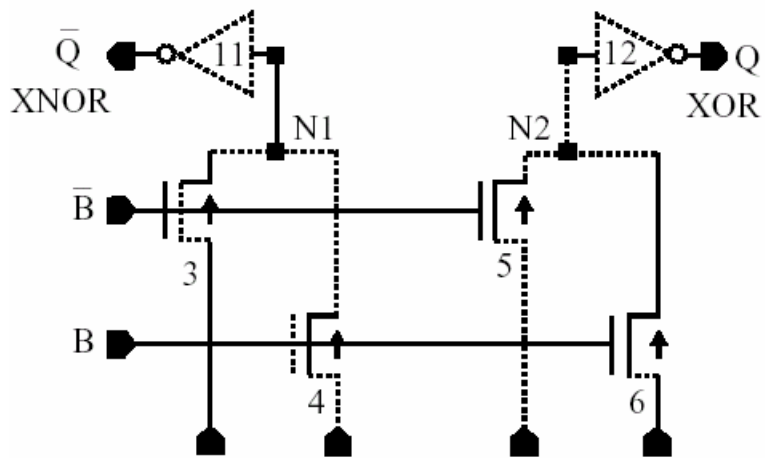


XOR-NXOR gate

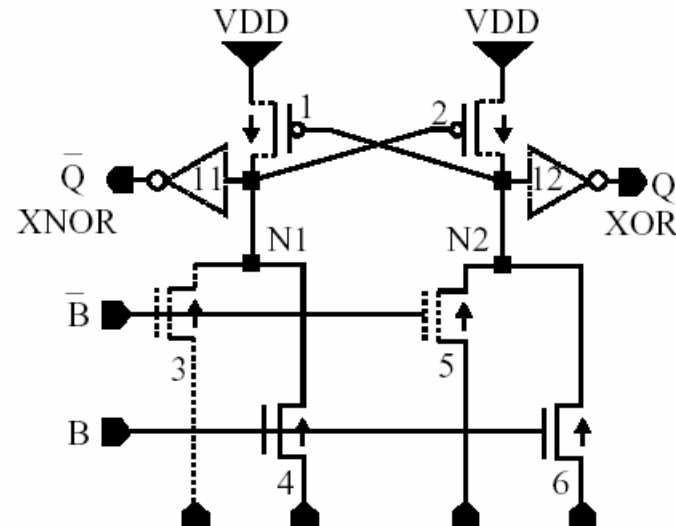
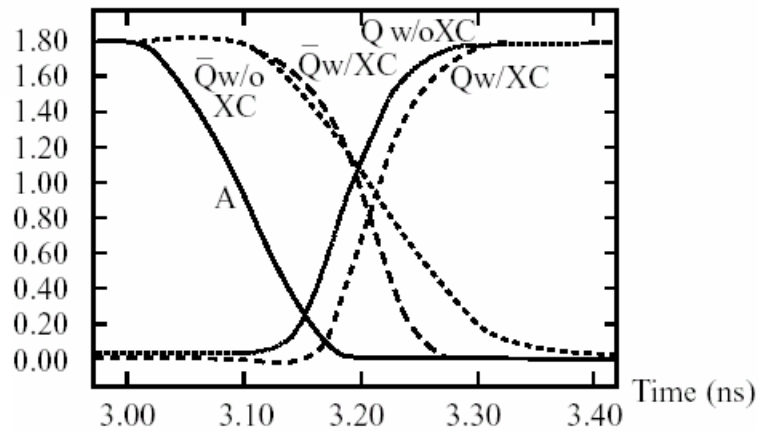
DCVSL Transient Response



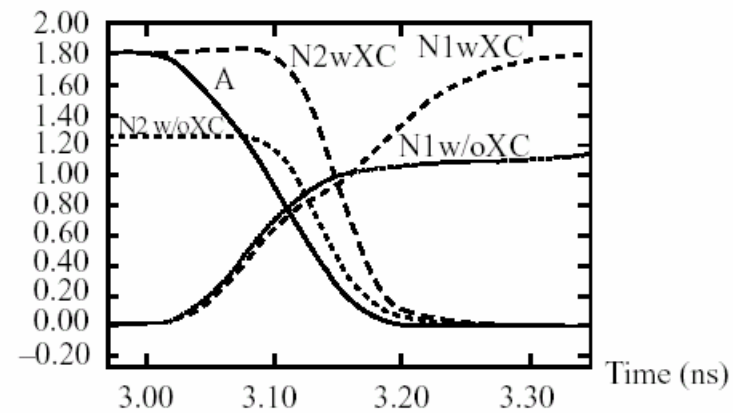
Complementary Pass Gate Logic (CPL)



Voltage (V)



Voltage (V)





Pass-gate Logic issues

- Limited fan-in
- Excessive fan-out
- Noise vulnerability (not restoring)
- Supply voltage offset/bias vulnerability
- Decode exclusivity (else short-circuit!)
- Poor high voltage levels if NMOS-only
- Body effect



Pass-Gate Logic Rules of Thumb

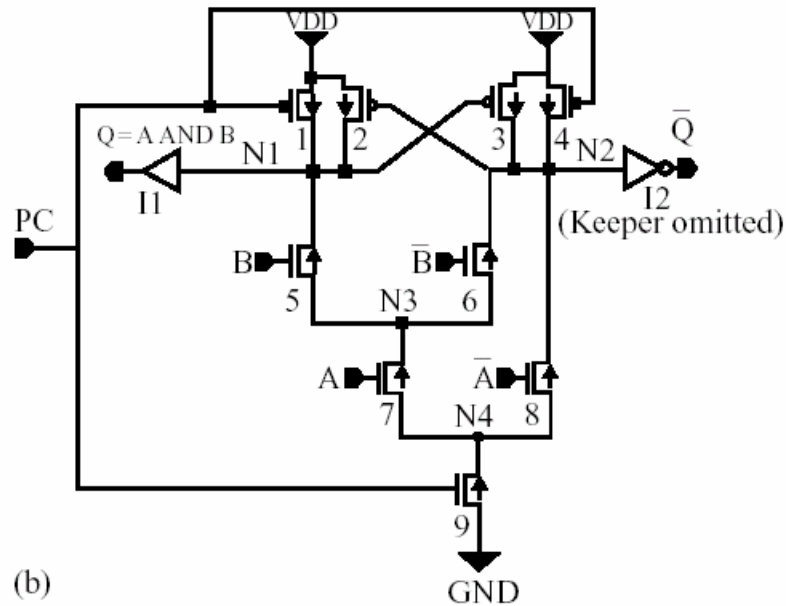
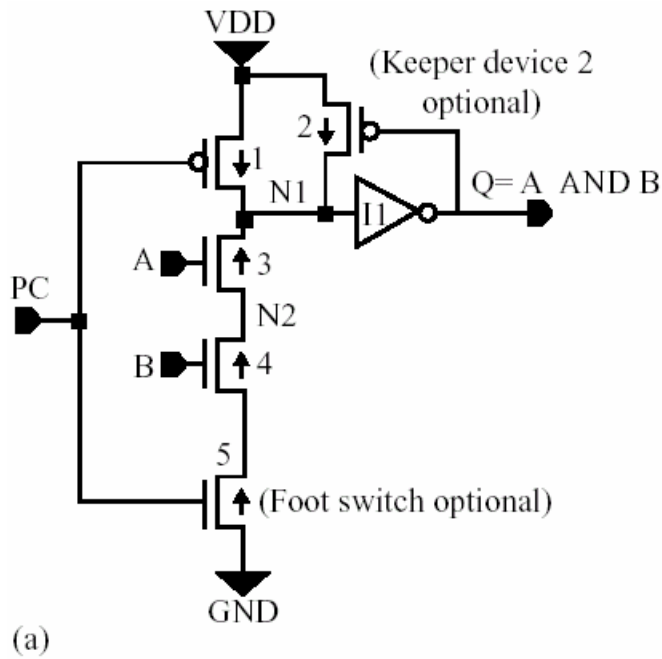
- Pass-logic may consume half the power of static logic. But be careful of V_t drop resulting in static leakage.
- Pass-gate logic is not appropriate when long interconnects separate logic stages or when circuits have high fan-out load (use buffering).



Dynamic Logic

- Idea – use the low leakage of FETs to store charge instead of moving current. Provides higher density, faster operation at the cost of reduced noise immunity and tricky design...
- Domino is by far the most common style in CMOS

Domino logic (single and dual-rail)





Dynamic Logic Rules of Thumb

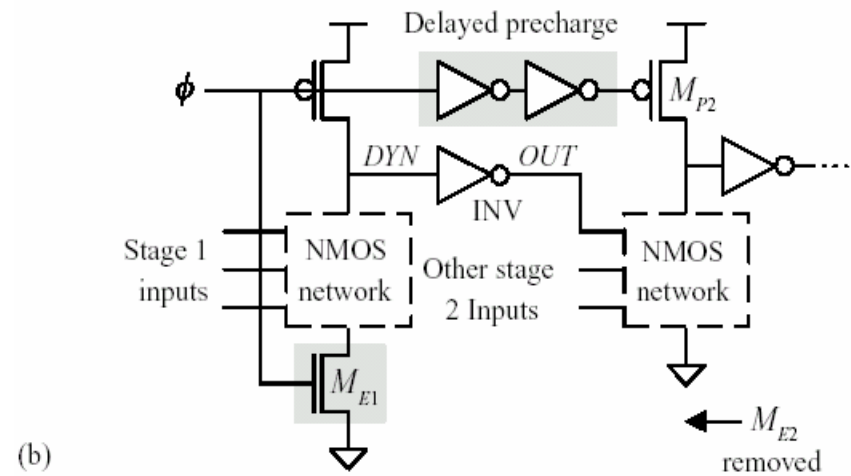
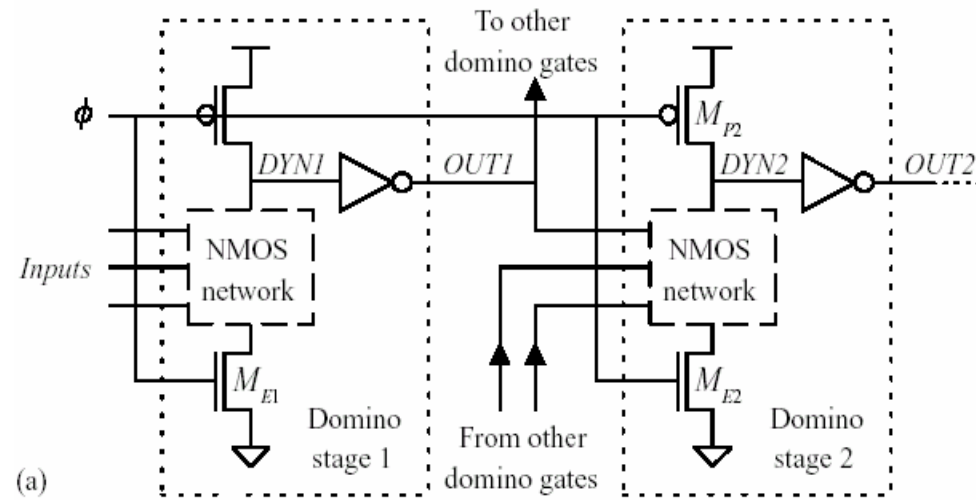
- Dynamic logic is best for wide OR/NOR structure (e.g. bit-lines), providing 50% delay improvement over static CMOS.
- Dynamic logic consumes 2x power due to its phase activity (unconditional pre-charging), not counting clock power.



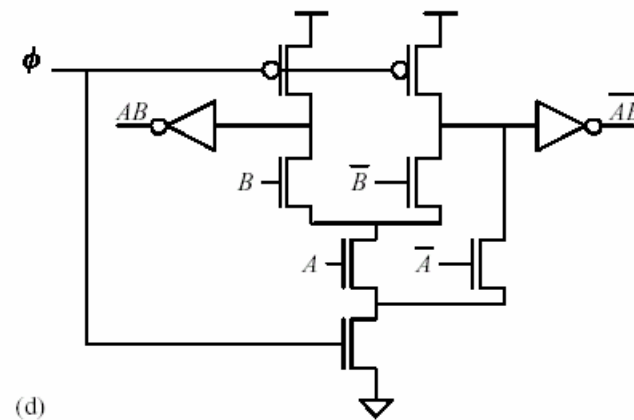
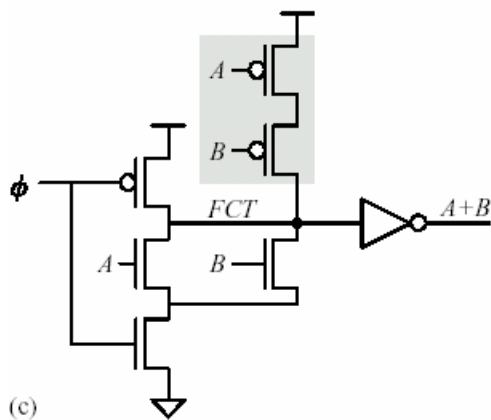
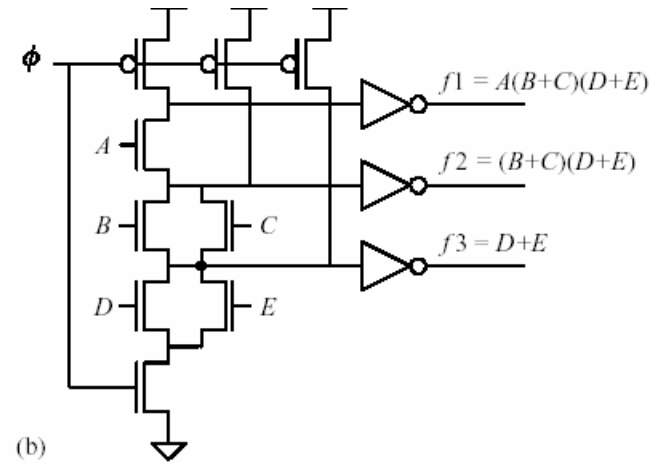
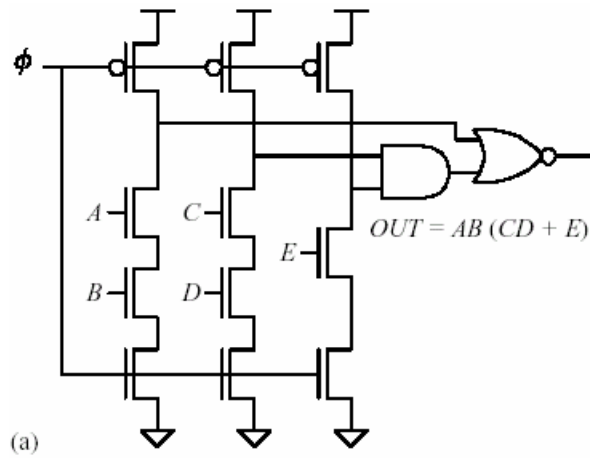
Domino Rules of Thumb

- Typical domino keepers have $W/L = 5-20\%$ of effective width of evaluate tree.
- Typical domino output buffers have a beta ratio of $\sim 6:1$ to push the switch point higher for fast rise-time but reduced noise margin.

Conventional and Delay-precharge domino



Advanced Domino Logic forms

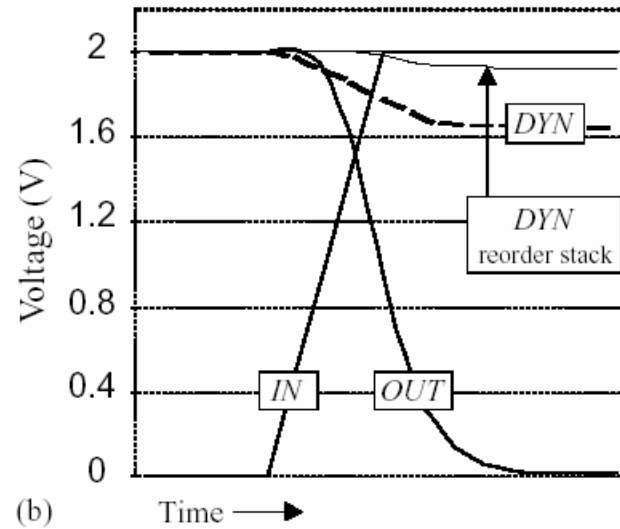
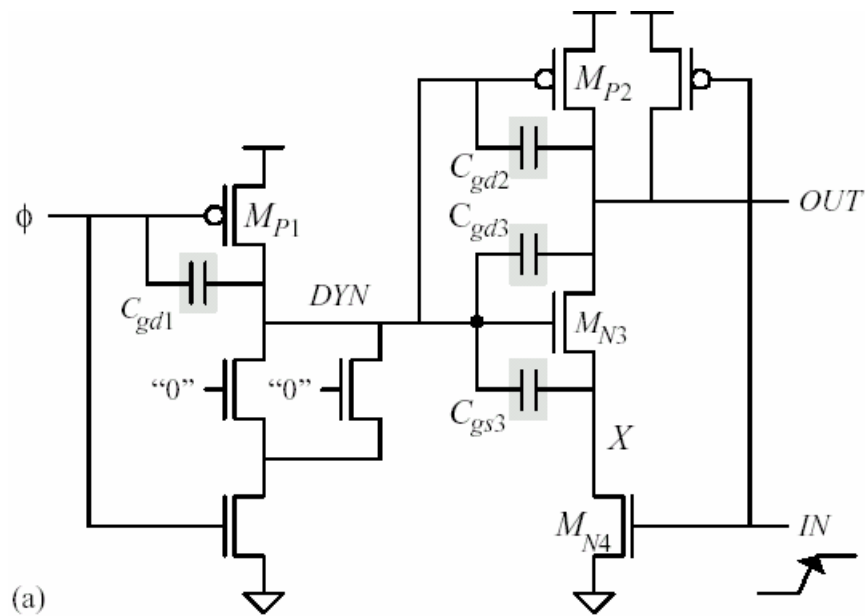




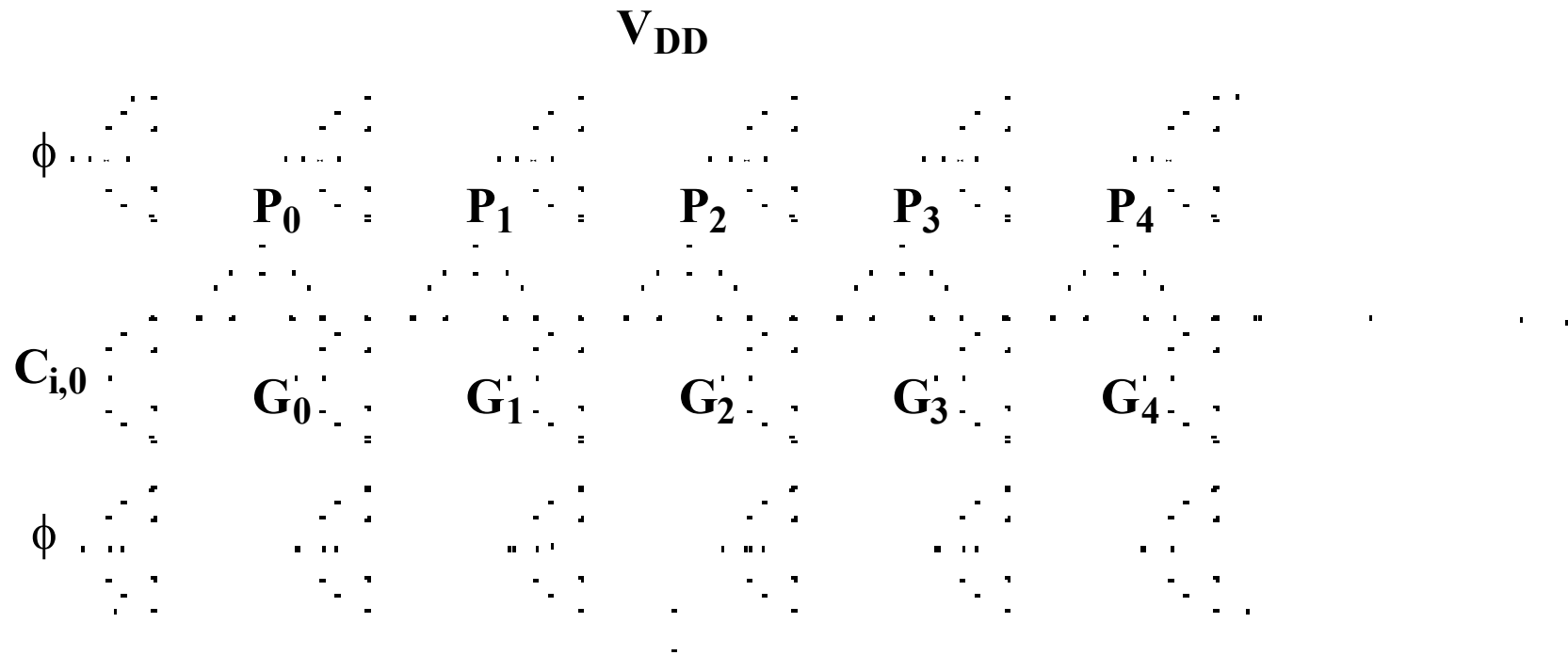
Concerns in Dynamic Logic

- Charge-sharing
- Charge-leakage
- Interconnect coupling
- Back-gate coupling
- Supply noise and variation

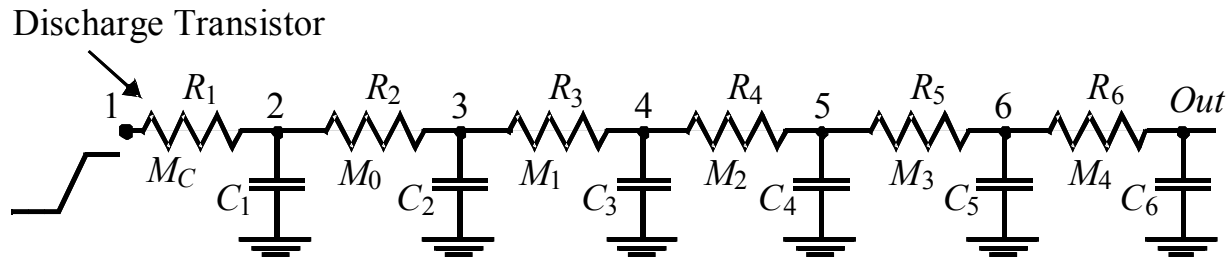
Back-gate coupling



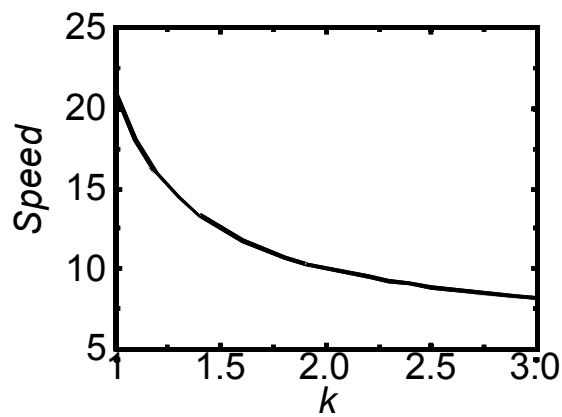
Manchester Carry Chain



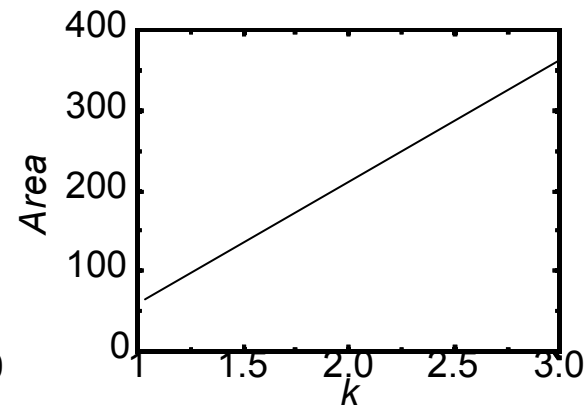
Sizing the Manchester Carry Chain



$$t = 0.69 \left(\sum_{i=1}^N R_i \left(\sum_{j=i}^N C_j \right) \right), R = R_{eq} / k, C = C_p + kC_n$$

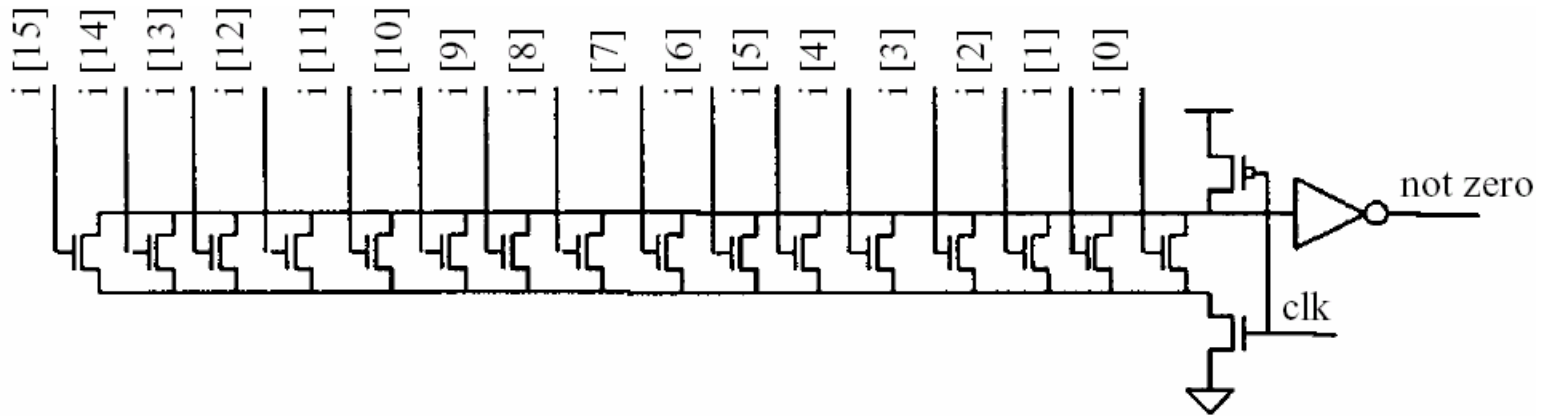


Speed (normalized by $0.69 RC$)



Area (in minimum size devices)

Domino Nor16 (zero-detect)

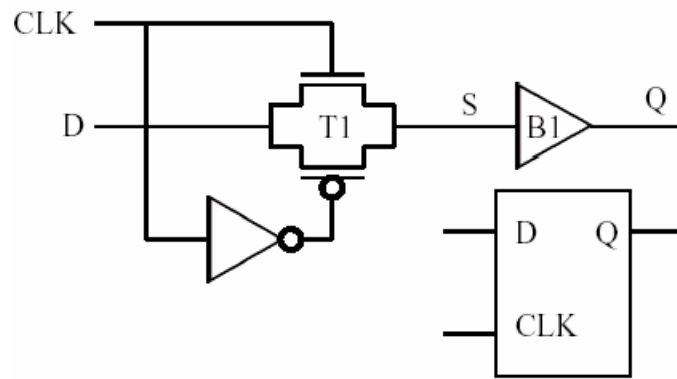




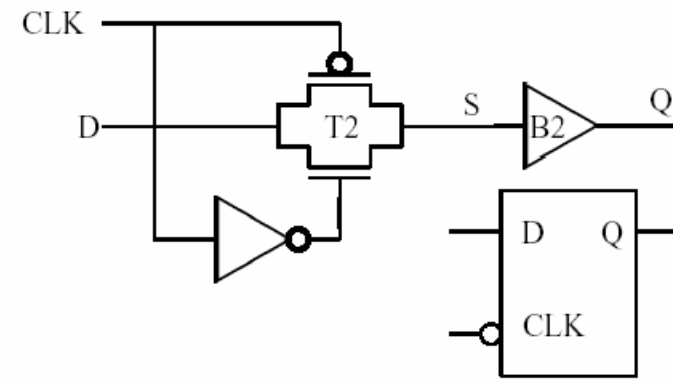
Flip-flops/latches/state elements

- Flip-flops occupy a special place in conventional digital design
 - Always Dynamic Behavior
 - Allow time coherence across large parts of the circuit
 - Preserve data across synchronization boundaries
 - --Inherently asynchronous design

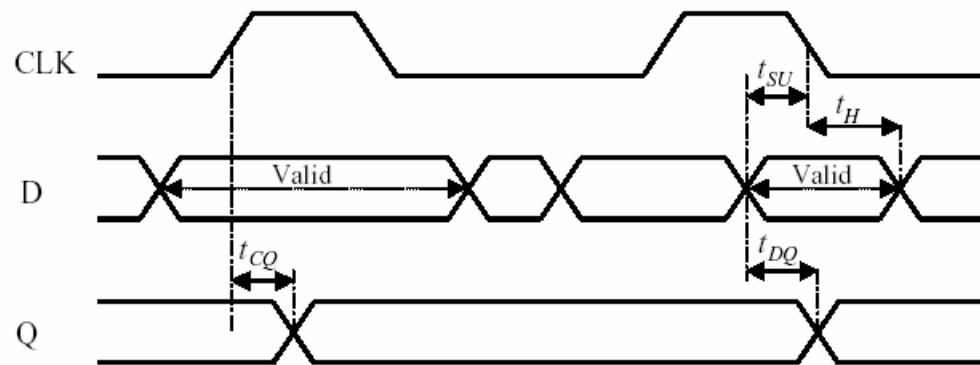
Level-sensitive latch pair



(a) The transparent high latch (THL)

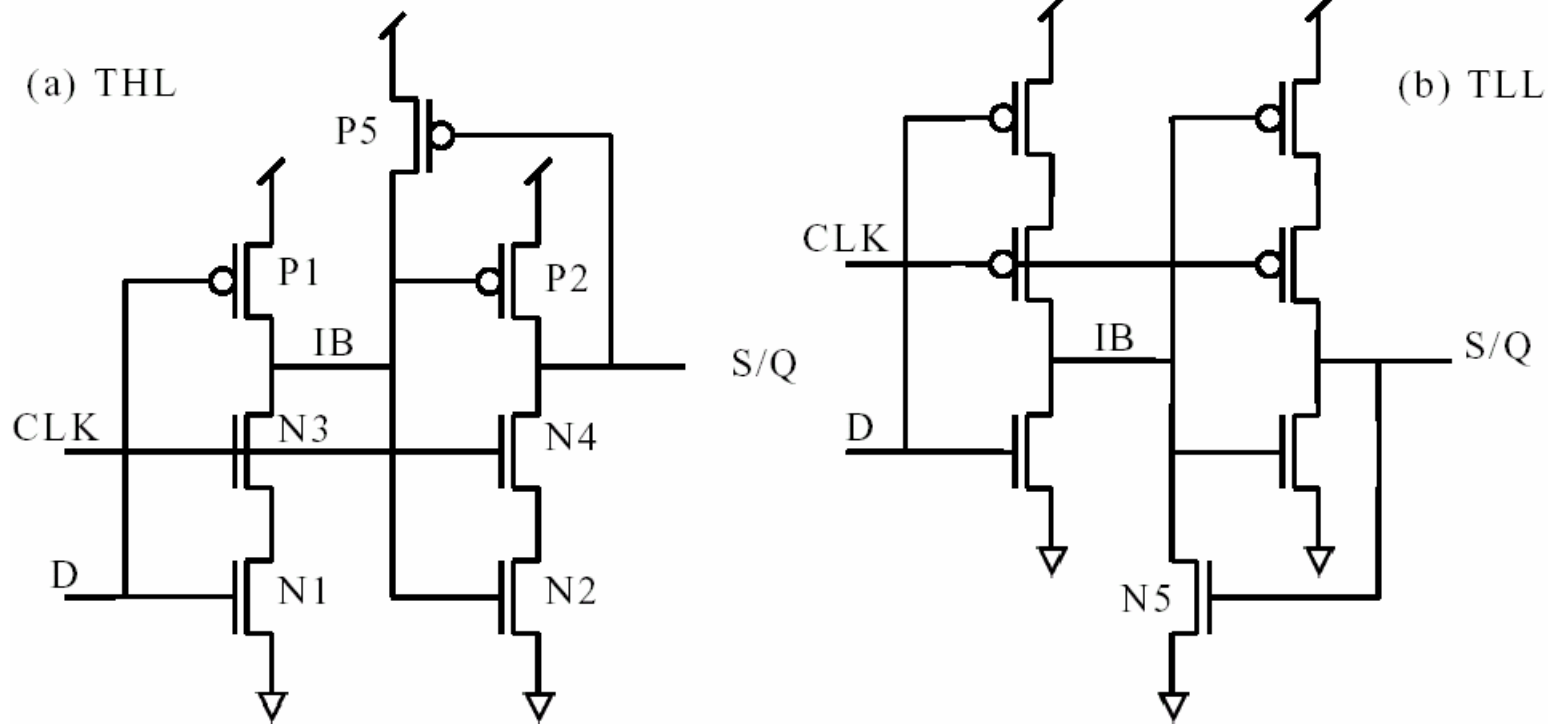


(b) The transparent low latch (TLL)

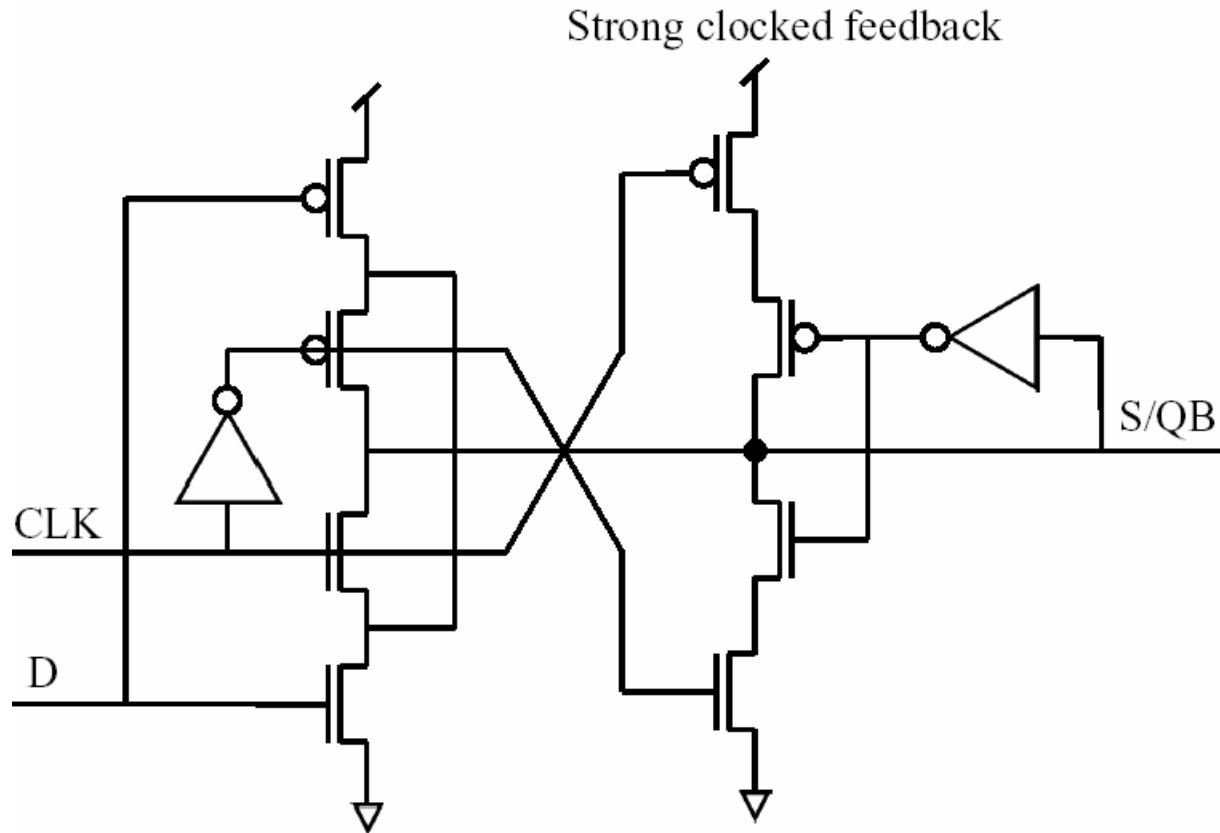


(c) Timing waveforms for the THL

Modified Svensson Latch of 21064

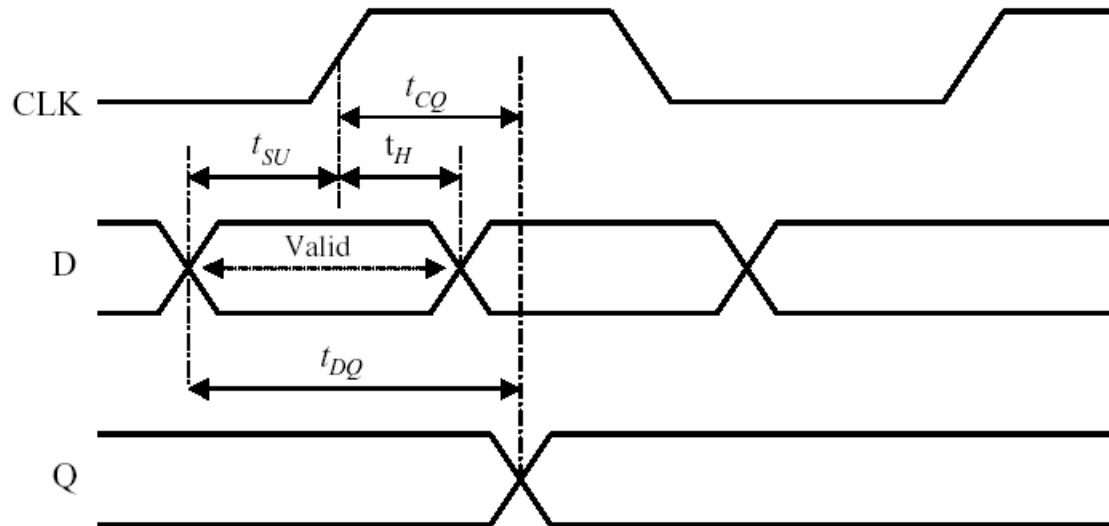
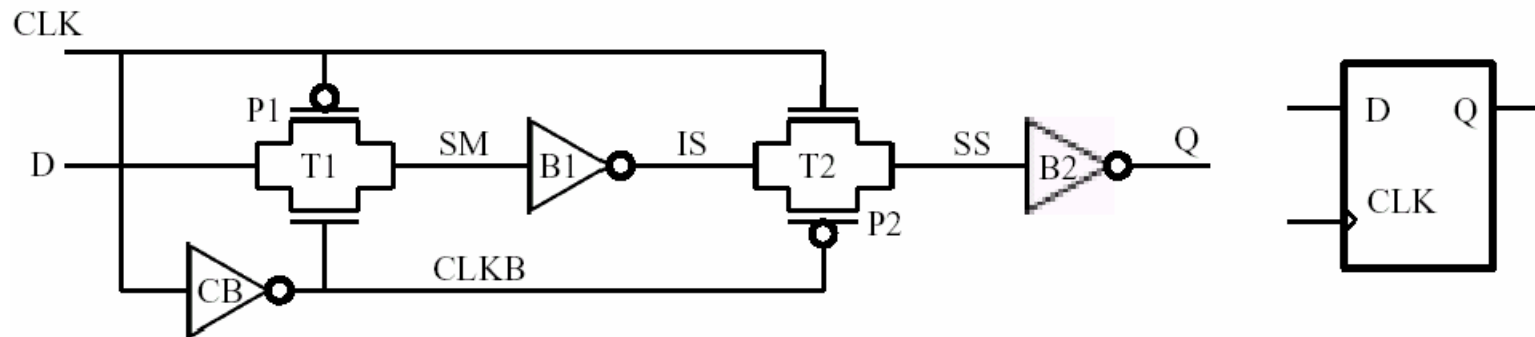


Tri-state based static latch

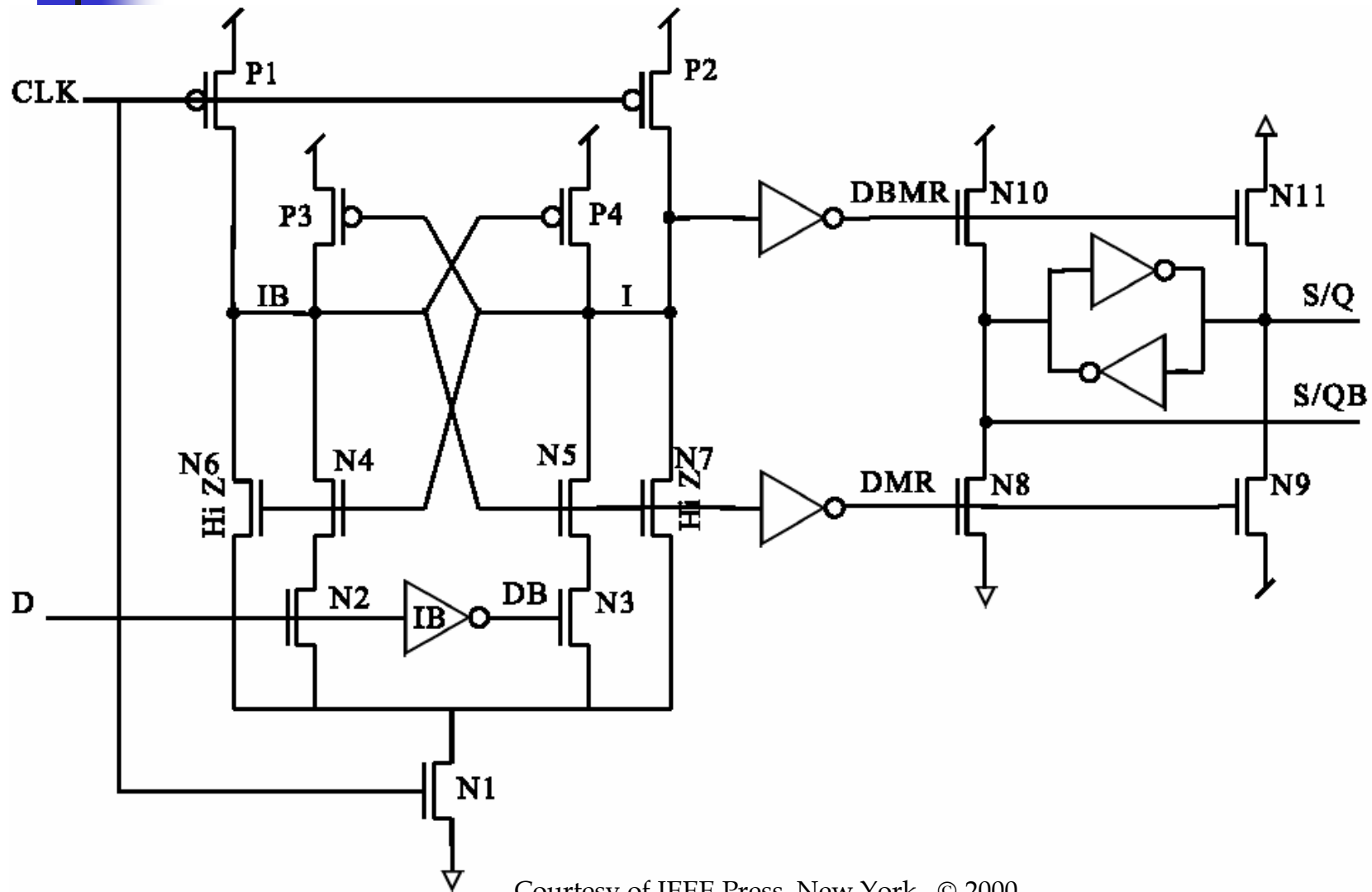


Stack order of the feedback is to take advantage of *good* charge - sharing

Master-slave (Dynamic) FF



Sense Amplifier-Based Flip-Flop



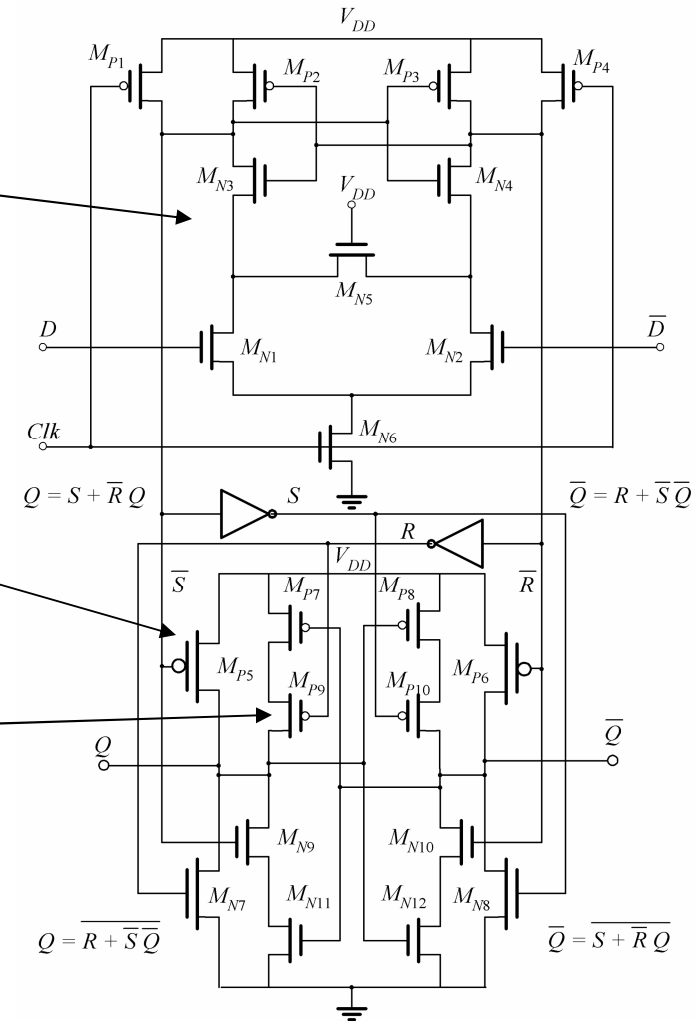
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Sense Amplifier-Based Flip-Flop

The first stage is unchanged sense amplifier
Second stage is sized to provide maximum switching speed

Driver transistors are large

Keeper transistors are small and disengaged during transitions

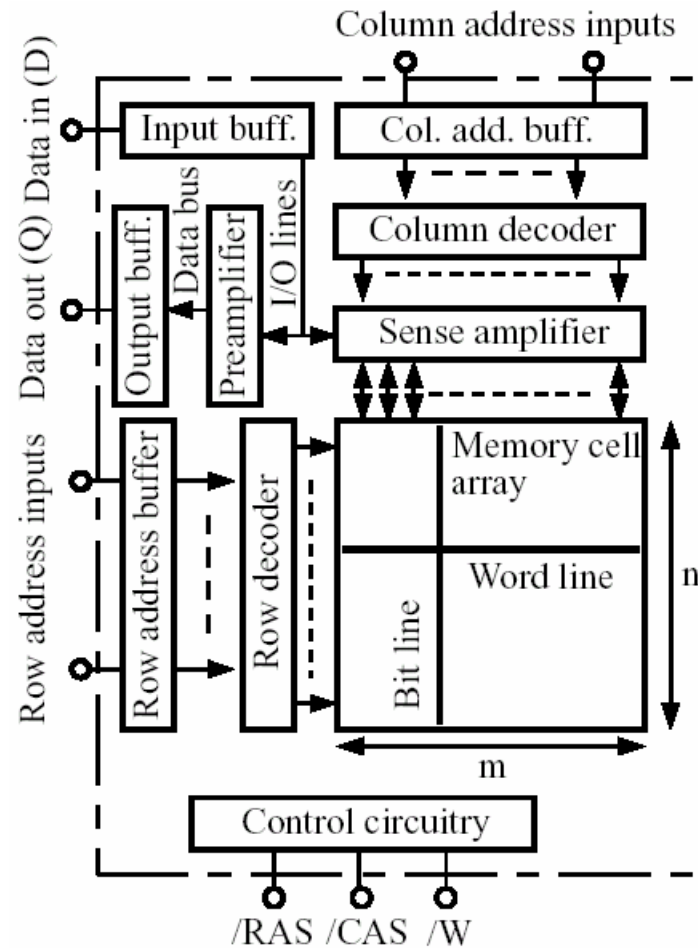




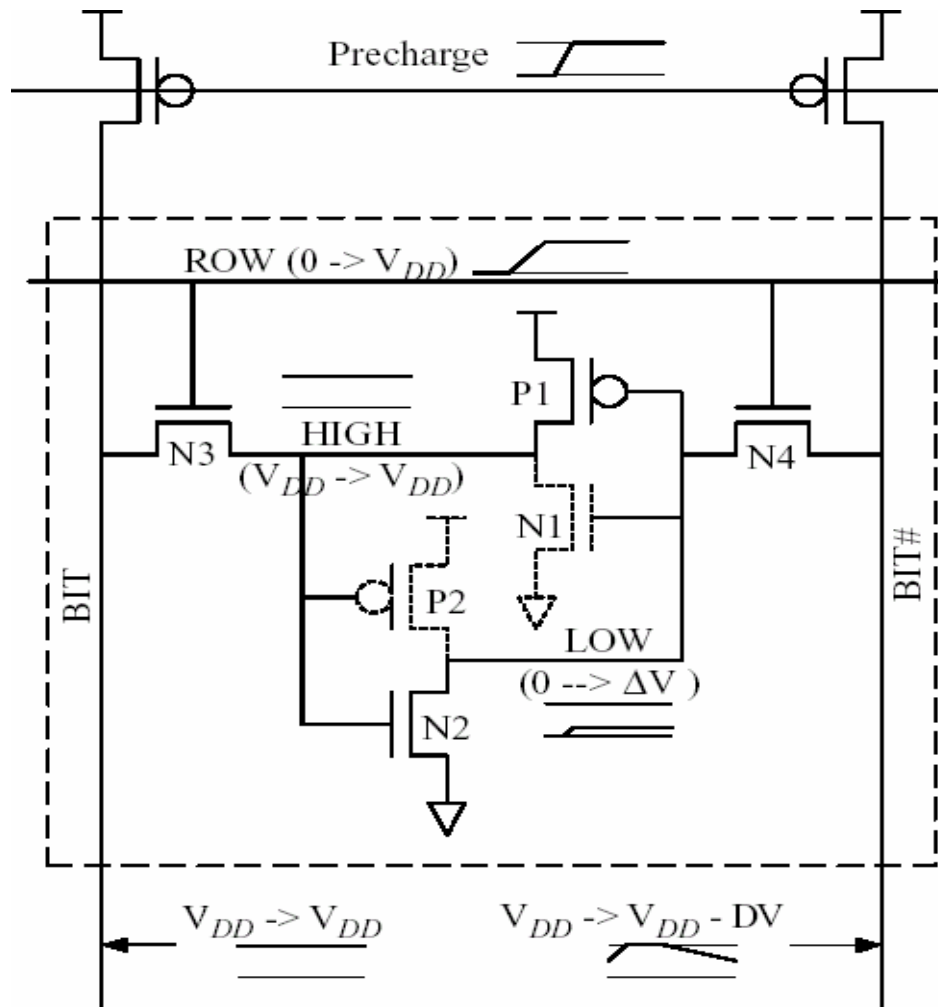
On-chip Memory

- Typically largest fraction of chip area
- Nearly always topologically organized (low Rent parameter <0.6)
- Simple wire/area planning rules

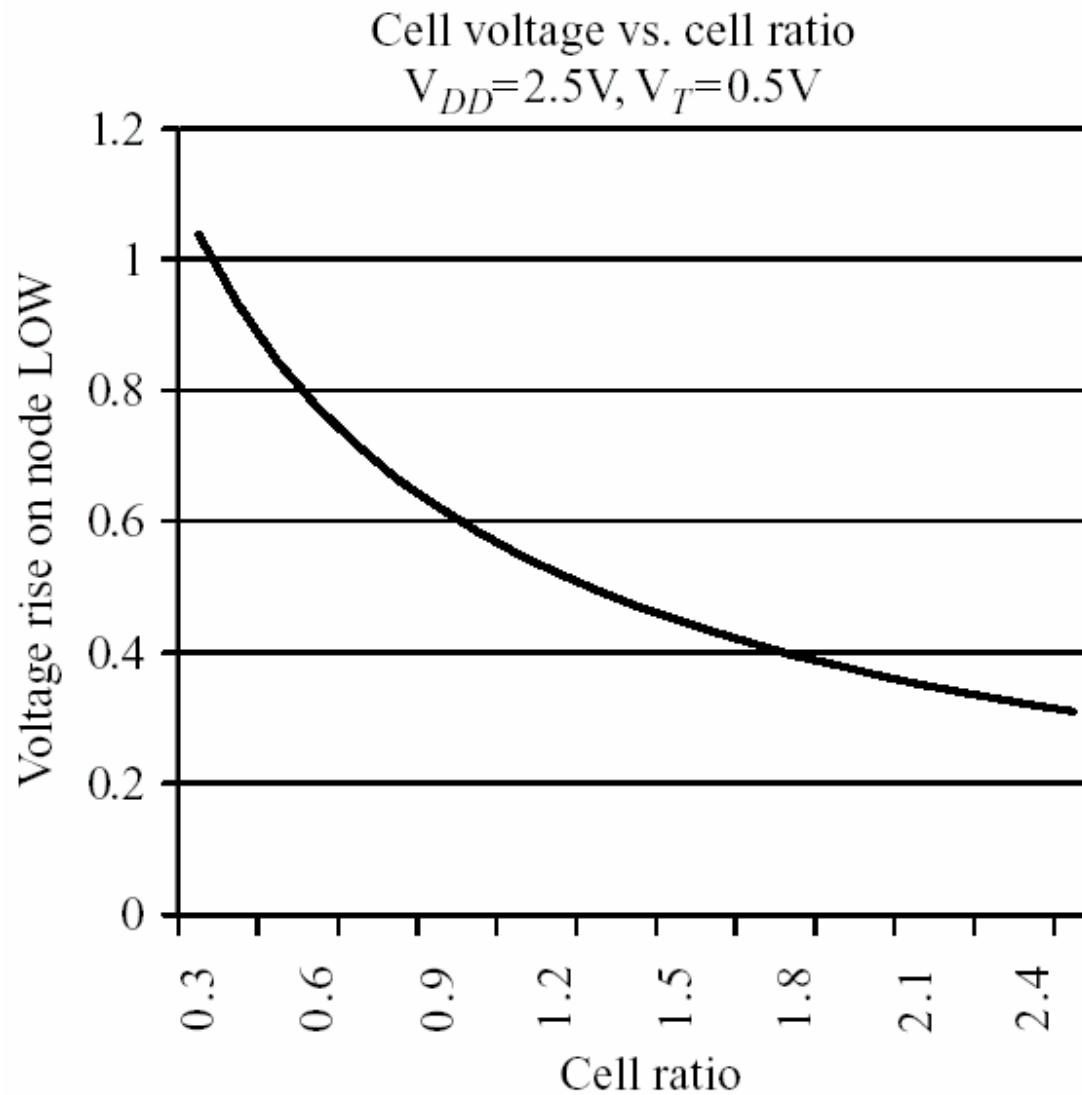
Generic memory block diagram



SRAM read operation

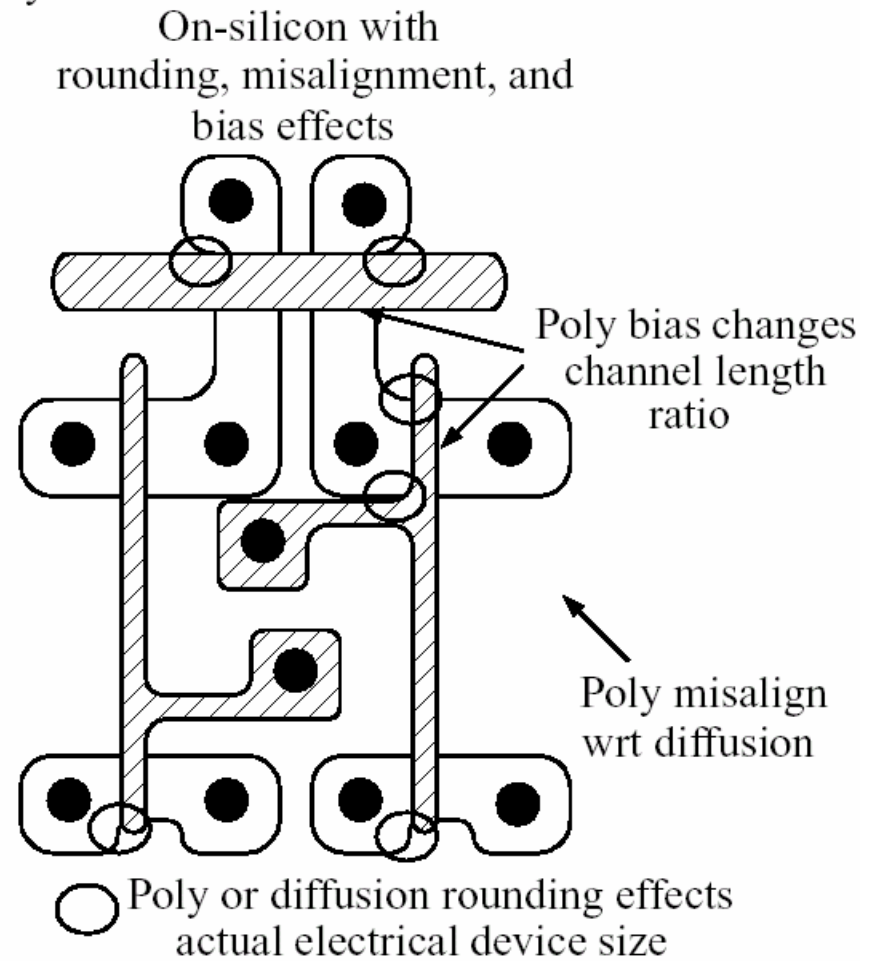
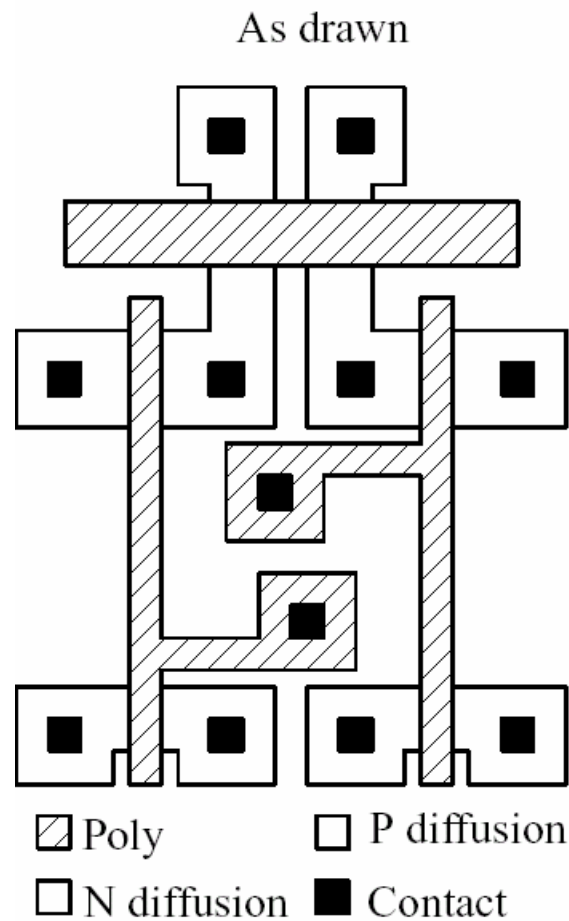


SRAM cell sized to avoid read-disturbance

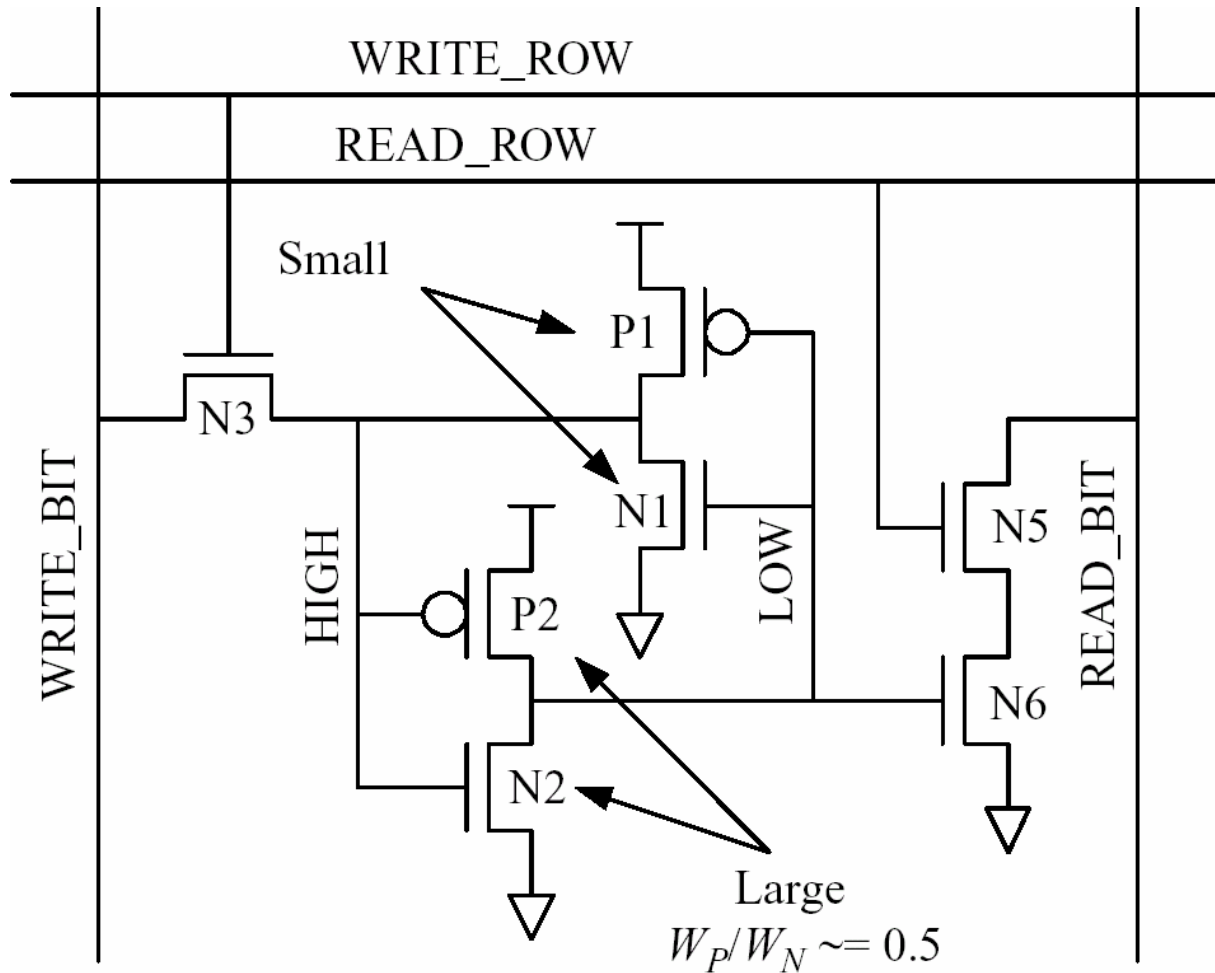


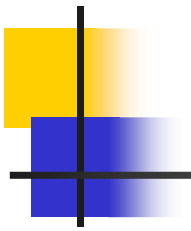
Realistic layout issues in SRAM cell

6T SRAM cell layout

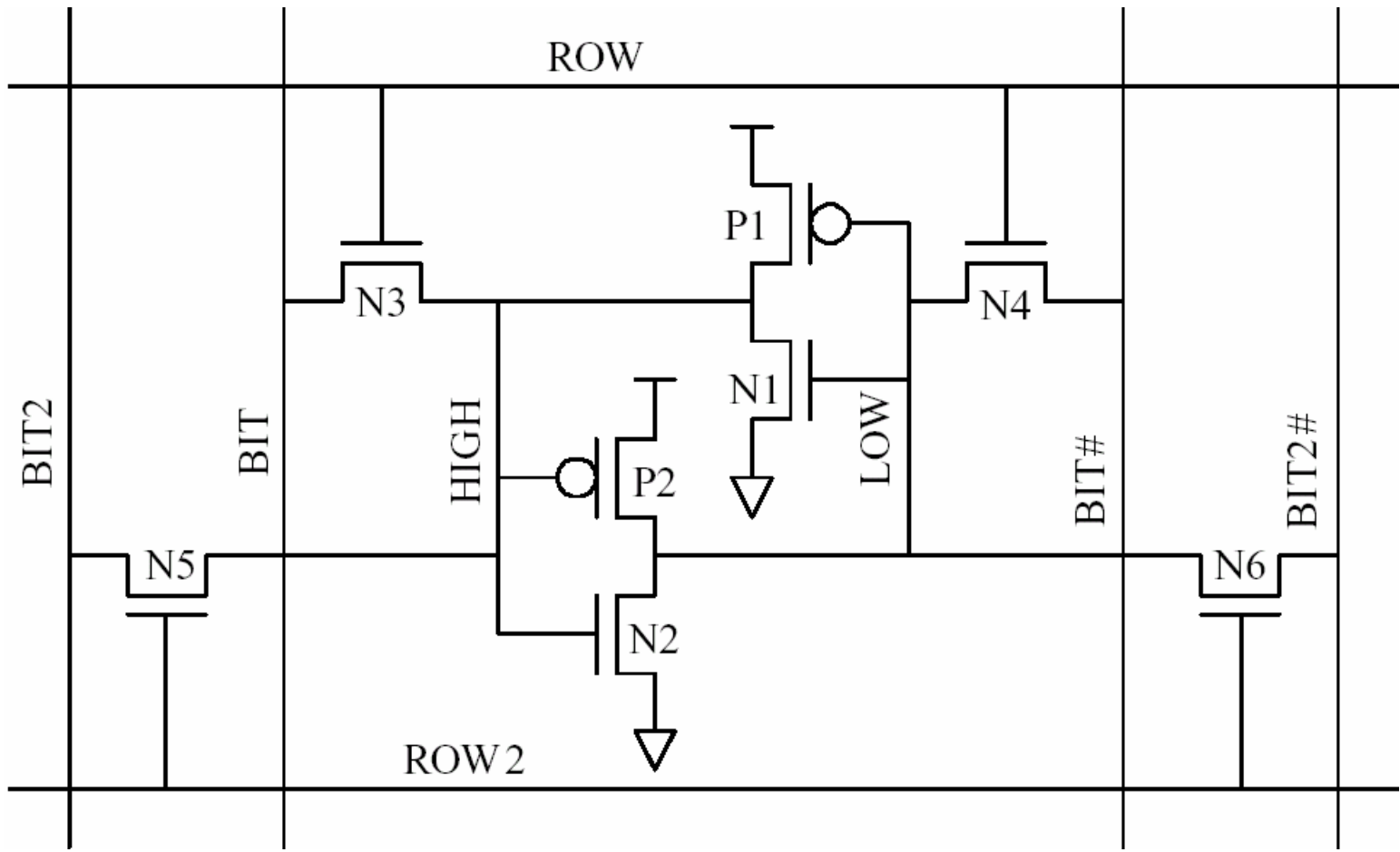


Asymmetric Read/Write Ports

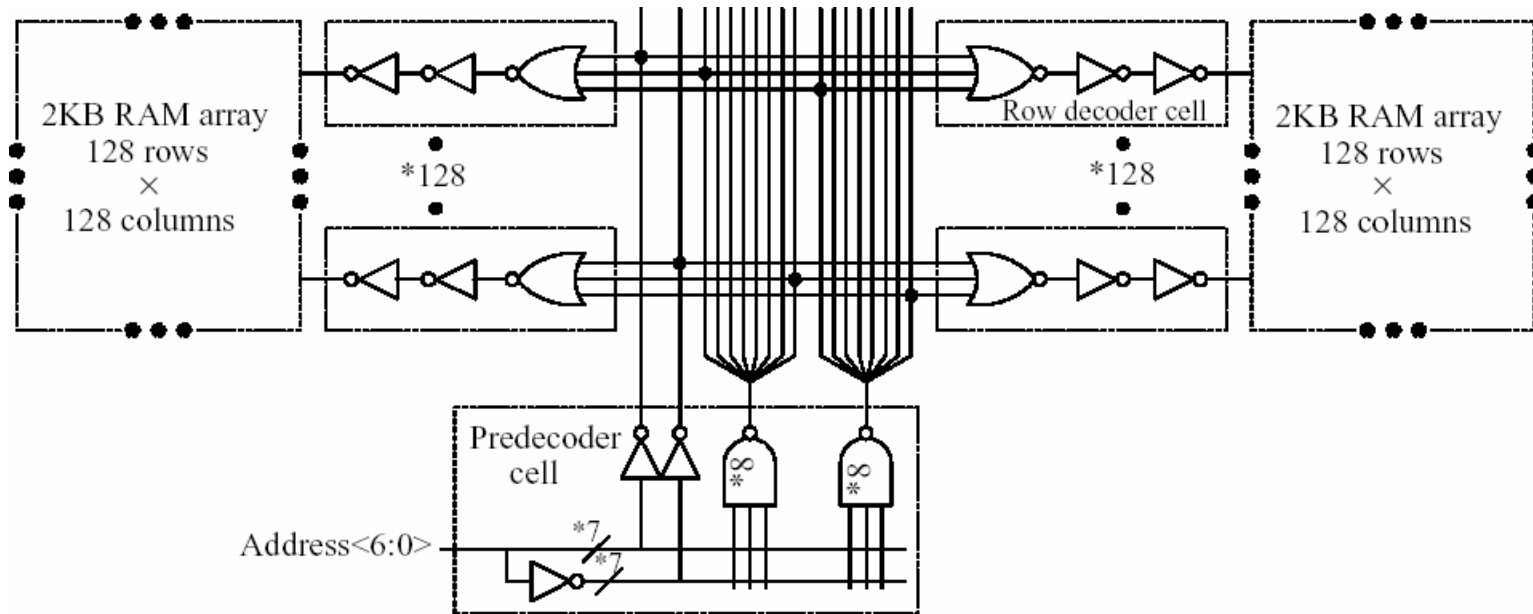




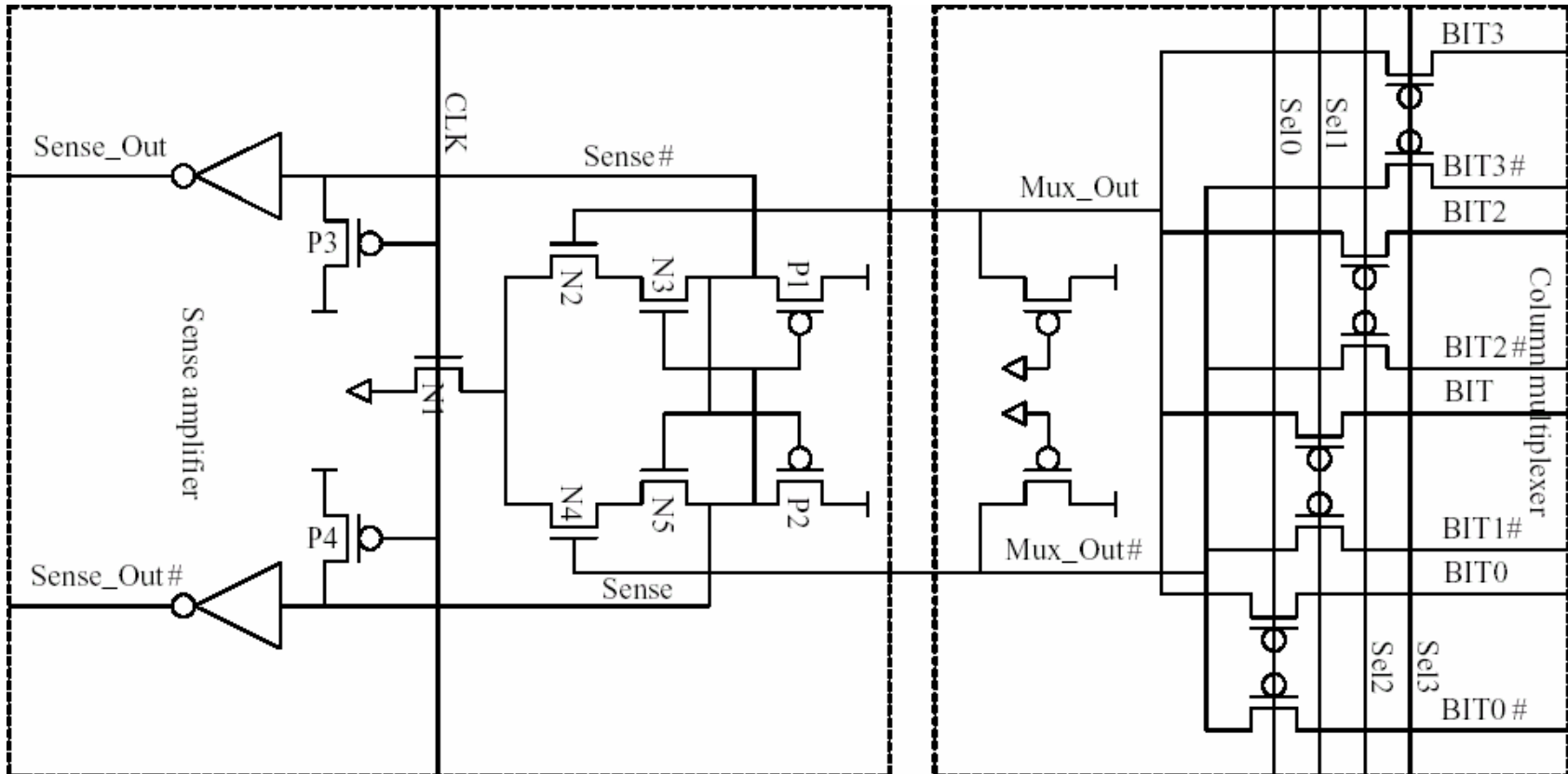
Multi-porting



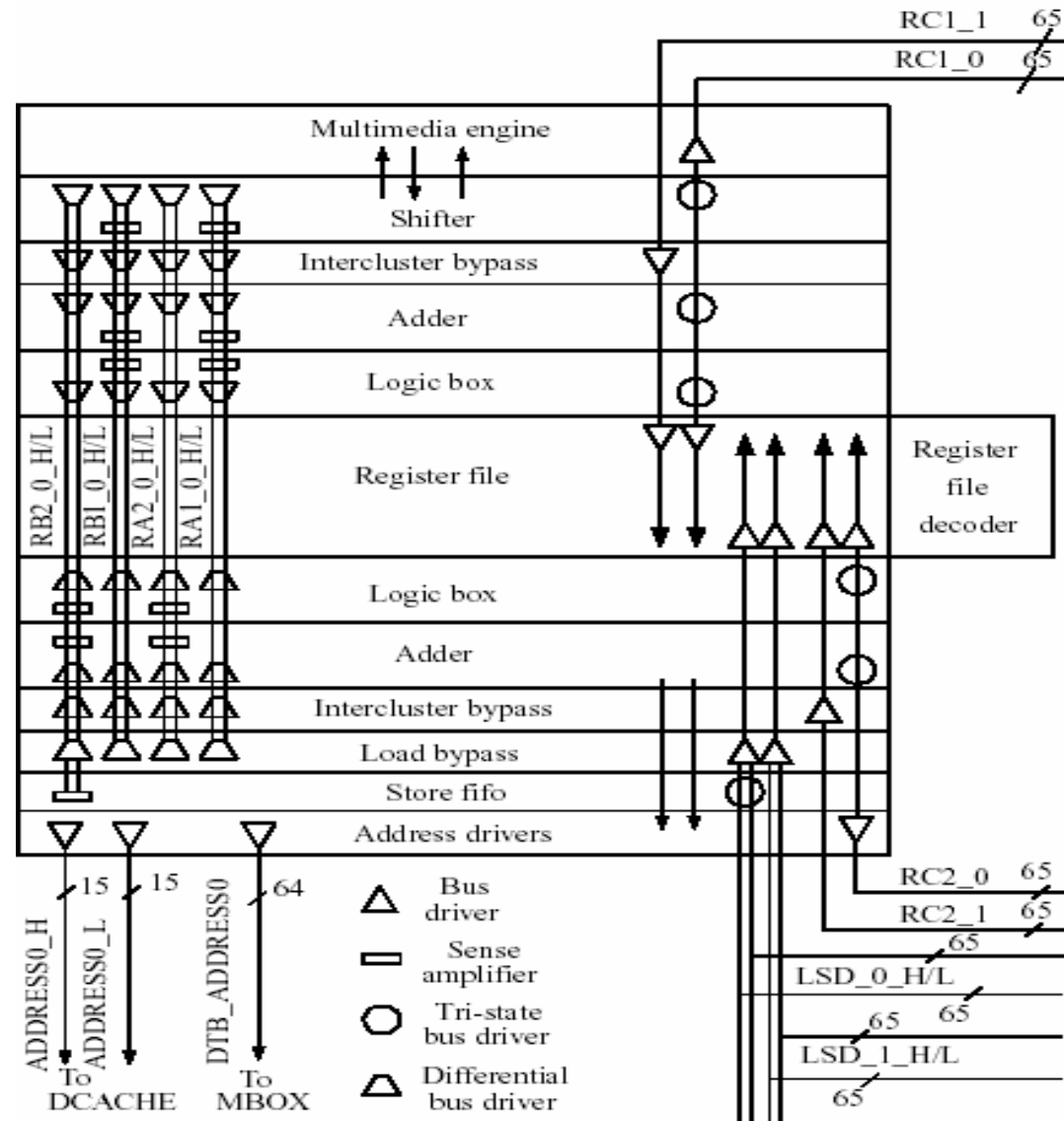
Split Row Decoder



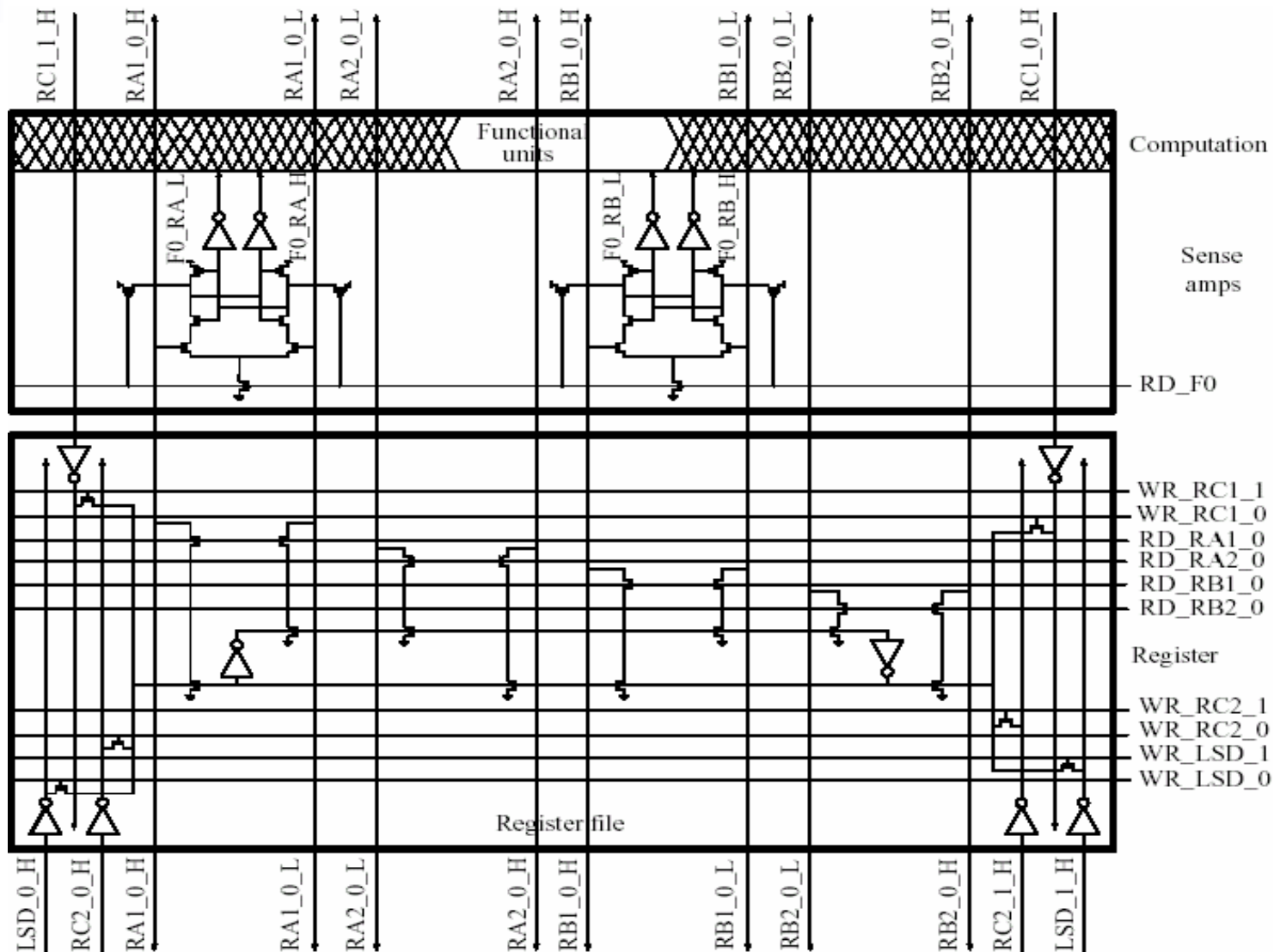
Column mux and sense-amp



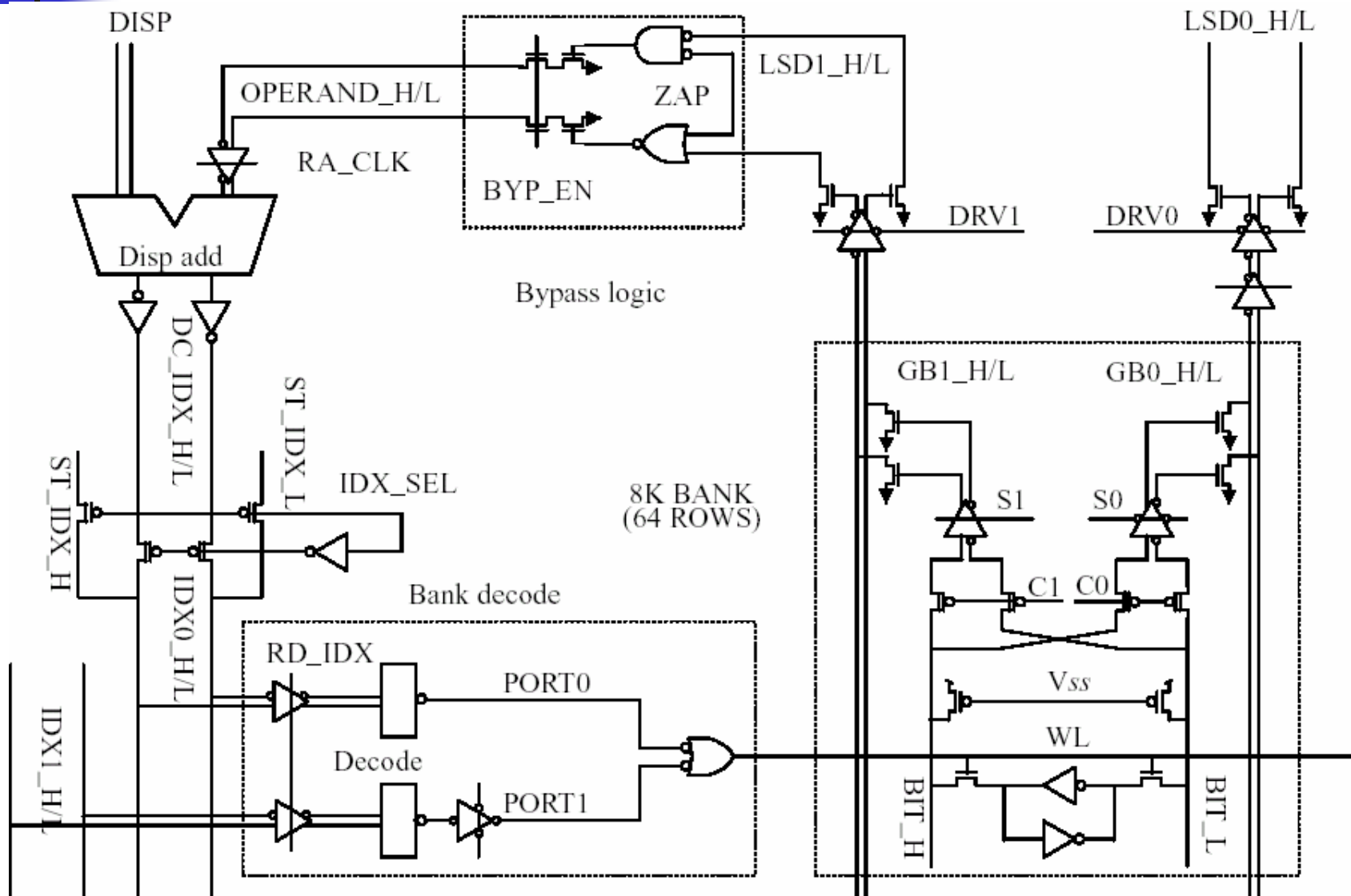
21264 Integer Unit floorplan



21264 Integer Register File cells



21264 L1 Dcache



21164 L2 Cache

